

Converter Architectures

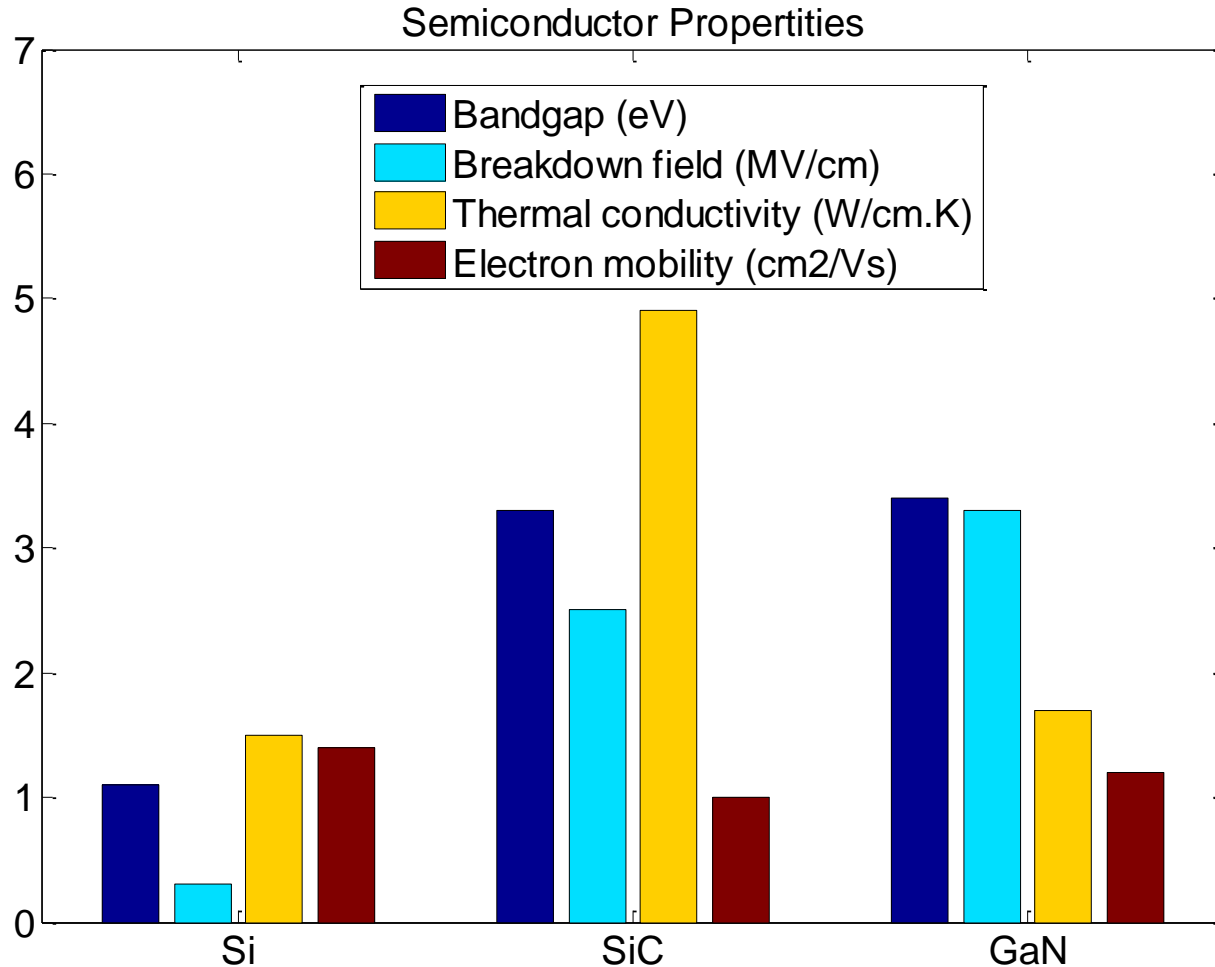
UK Centre for Power Electronics Annual Conference

Prof. Xibo Yuan, Prof. Andrew Forsyth, Prof. Paul Mitcheson, Dr David Yates, Dr Ian Laird, Dr Juan Manuel Arteaga, Dr Gerardo Calderon-Lopez, Dr Jun Wang, Mr Wenzhi Zhou, Dr Samer Aldhaher, Prof. Jon Clare

Overview of the Converter Architecture Project

- Project duration: 1st November 2017 to 31st October 2021.
- WP1 Converter Topology Investigation
- WP2 Passive Components
- WP3 Advanced Control
- WP4 Design Optimisation
- WP5 Demonstrator

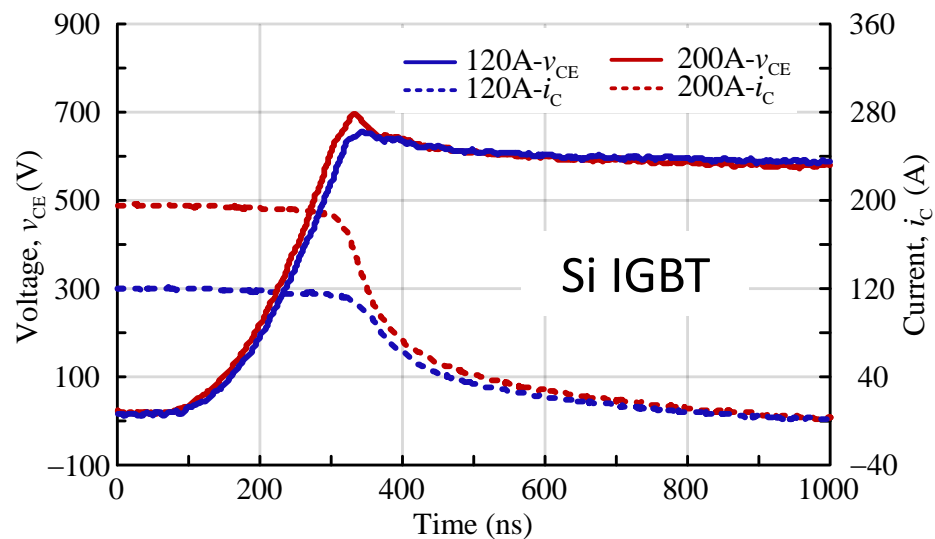
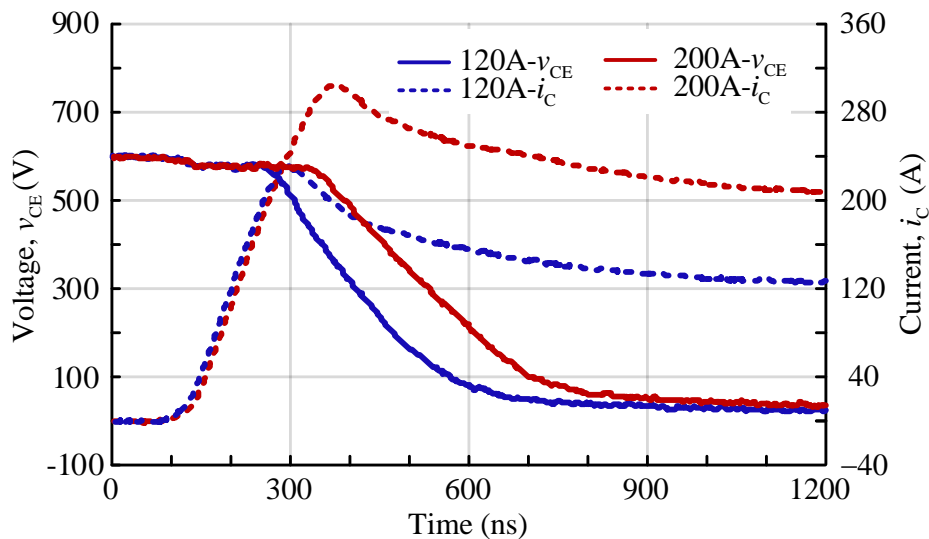
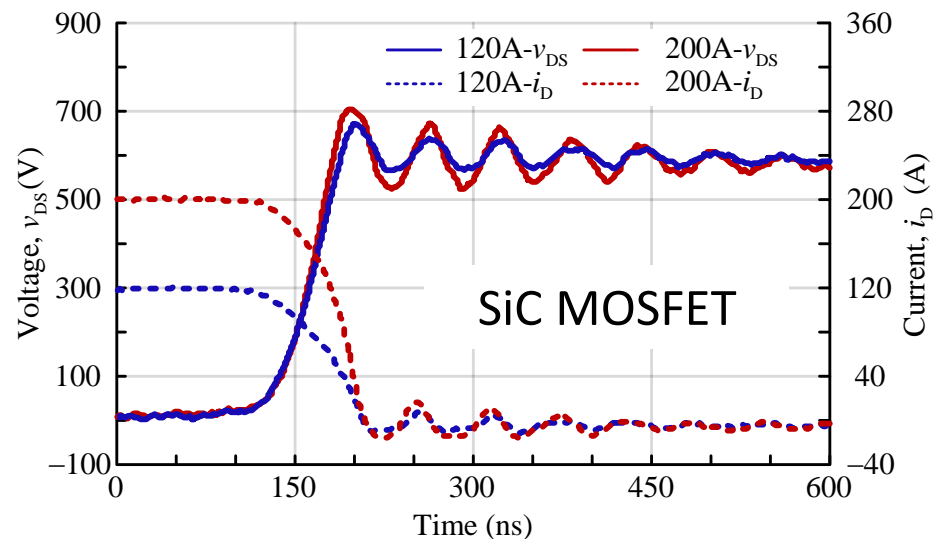
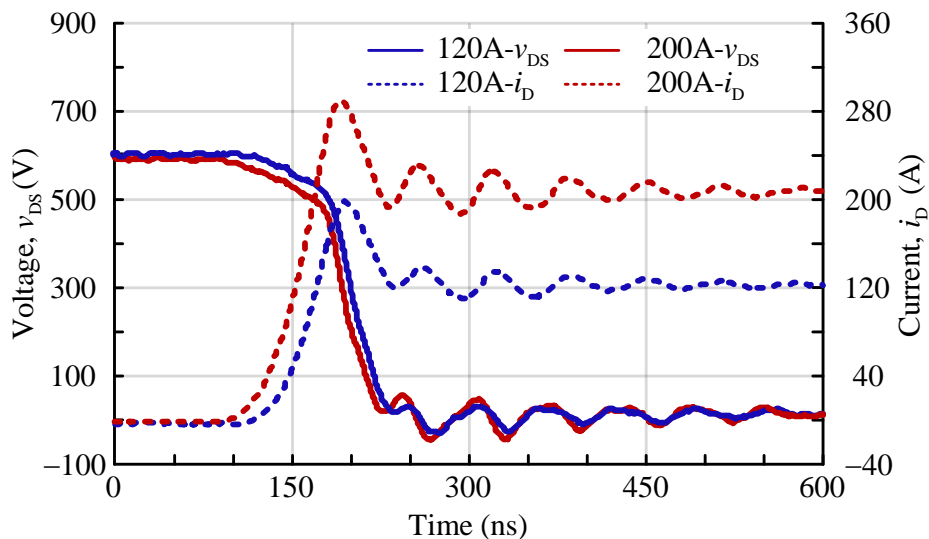
Opportunities: Wide-bandgap Material Properties



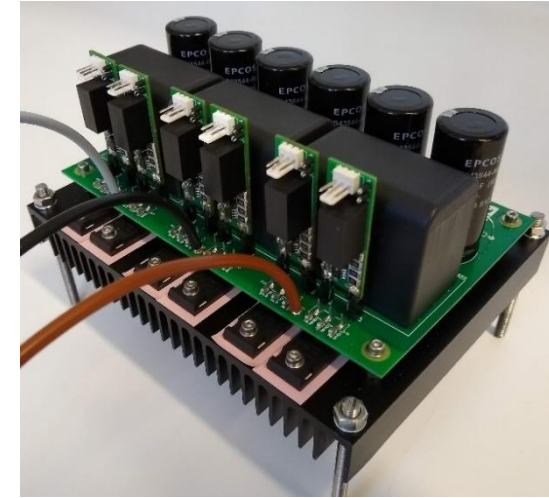
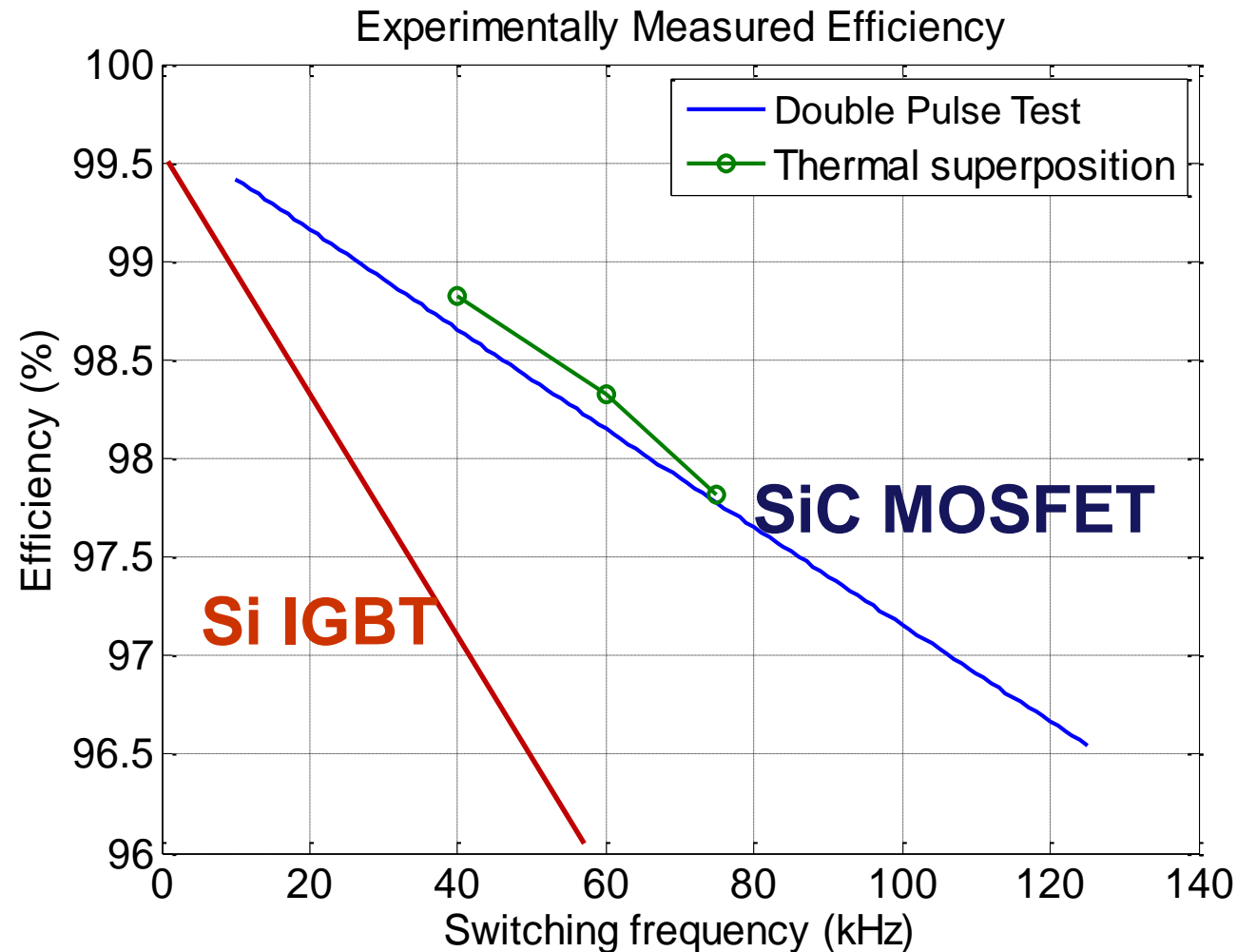
Higher
Speed
Voltage
Temperature

X. Yuan, I. Laird, S. Walder, “Opportunities, Challenges and Potential Solutions in the Application of Fast-Switching Silicon Carbide (SiC) Power Devices and Converters”, *IEEE Transactions on Power Electronics*, vol.36, no.4, pp. 3925-3945, Apr. 2021.

High Power Module (1700V, 300A) Switching

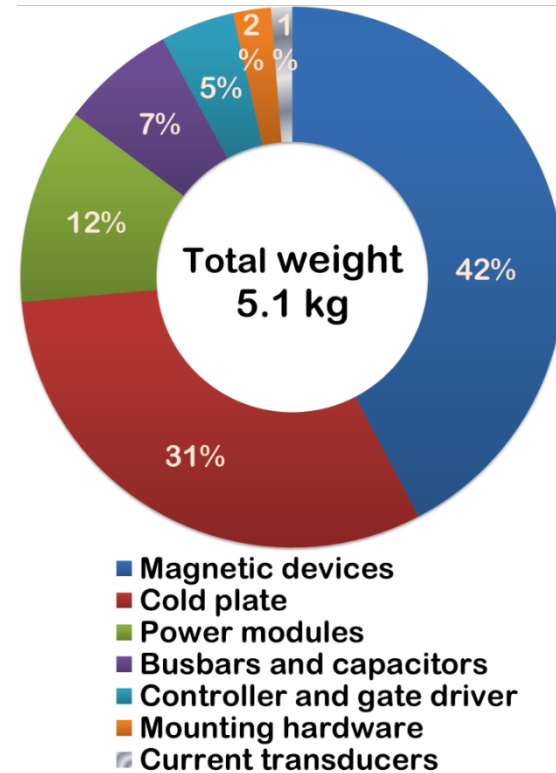
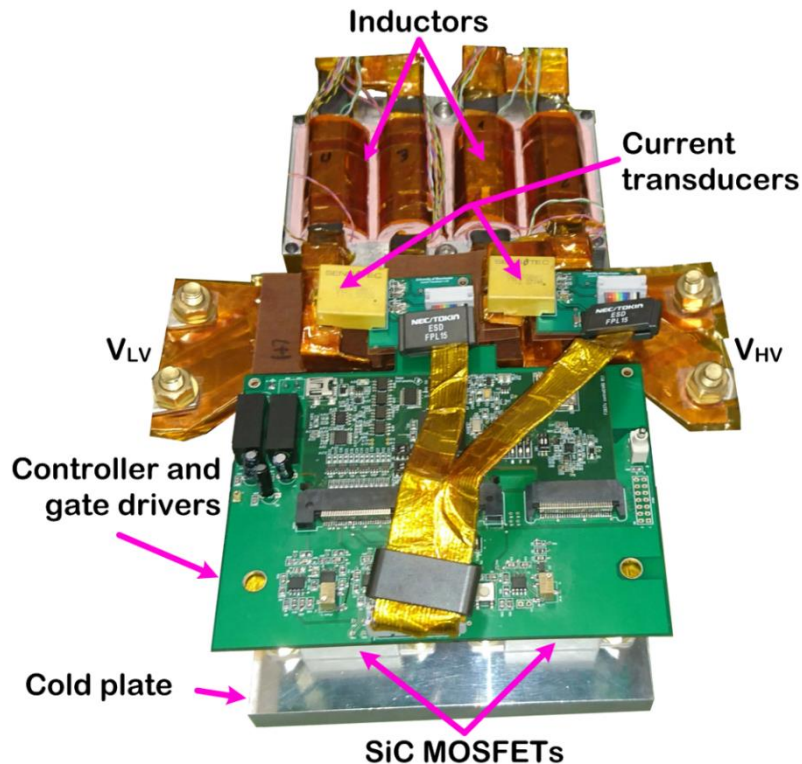


Opportunities: Efficiency Improvement



- Reduce harmonic-induced losses
- Reduce filtering components (inductors, dc-link caps)
- High fundamental frequency drives

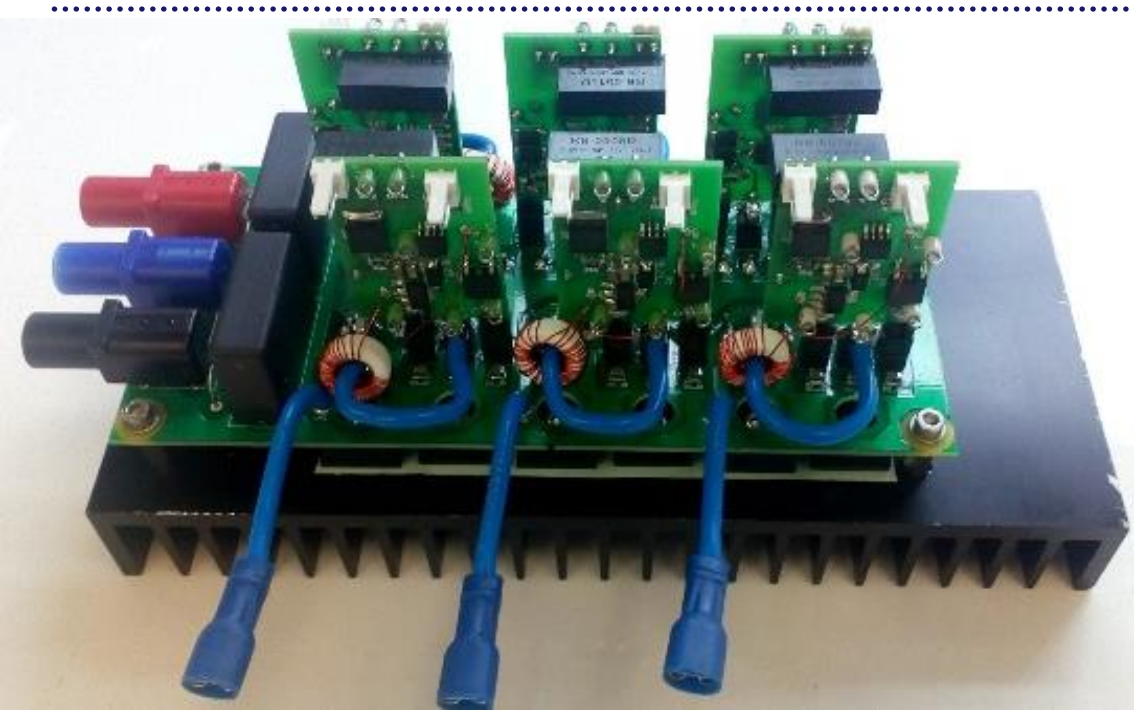
High Power Density DC/DC Converter



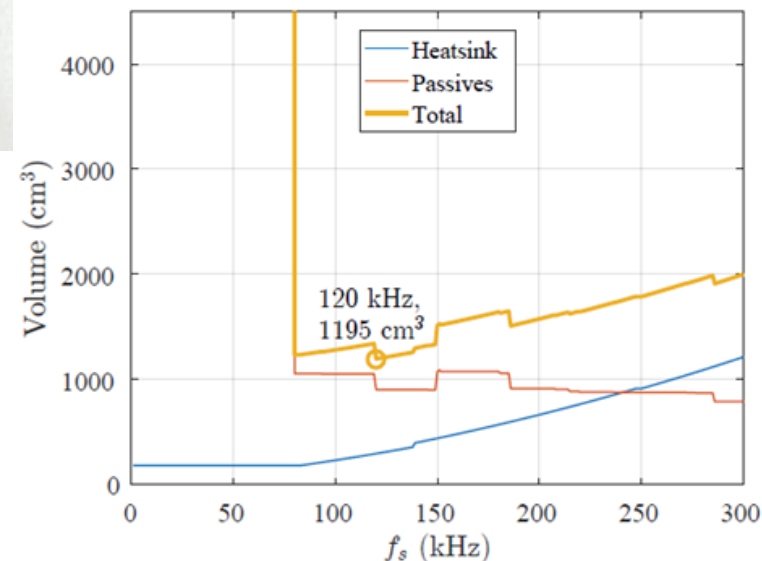
**80 kW dual bi-directional interleaved DC/DC converter and its breakdown of weight, 300-750 V, 115 kHz, 5.1 kg, 256×142×70 mm
2.6 L, 31.5 kW/L ,15.7 kW/kg**

G. Lopez, J. Scoltock, Y. Wang, I. Laird, X. Yuan, A. Forsyth, "Power-dense Bi-directional DC-DC Converters with High Performance Inductors", *IEEE Transactions on Vehicular Technology*, vol.68, no.12, pp. 11439-11448, Dec. 2019.

High Temperature SiC BJT Converter

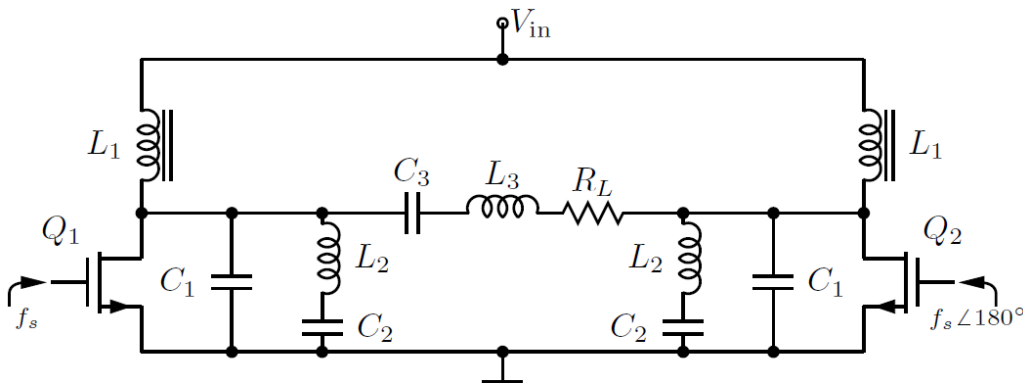
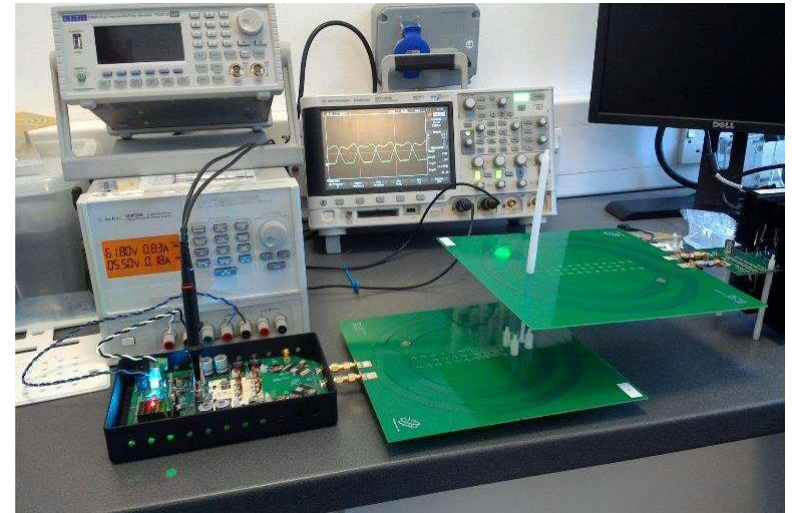


A 5kW ‘high-temperature’ (180°C junction temperature) SiC BJT based three-phase converter optimised holistically using a proposed design optimisation tool (EMI and line filters are not shown here).



I. Laird, X. Yuan, B. Jin, N. McNeill, “High Temperature Design Optimization of DC/AC Power Converters Using SiC BJTs”, in Proc. IEEE ECCE’18 Conf., pp.1-7, Sept. 2018.

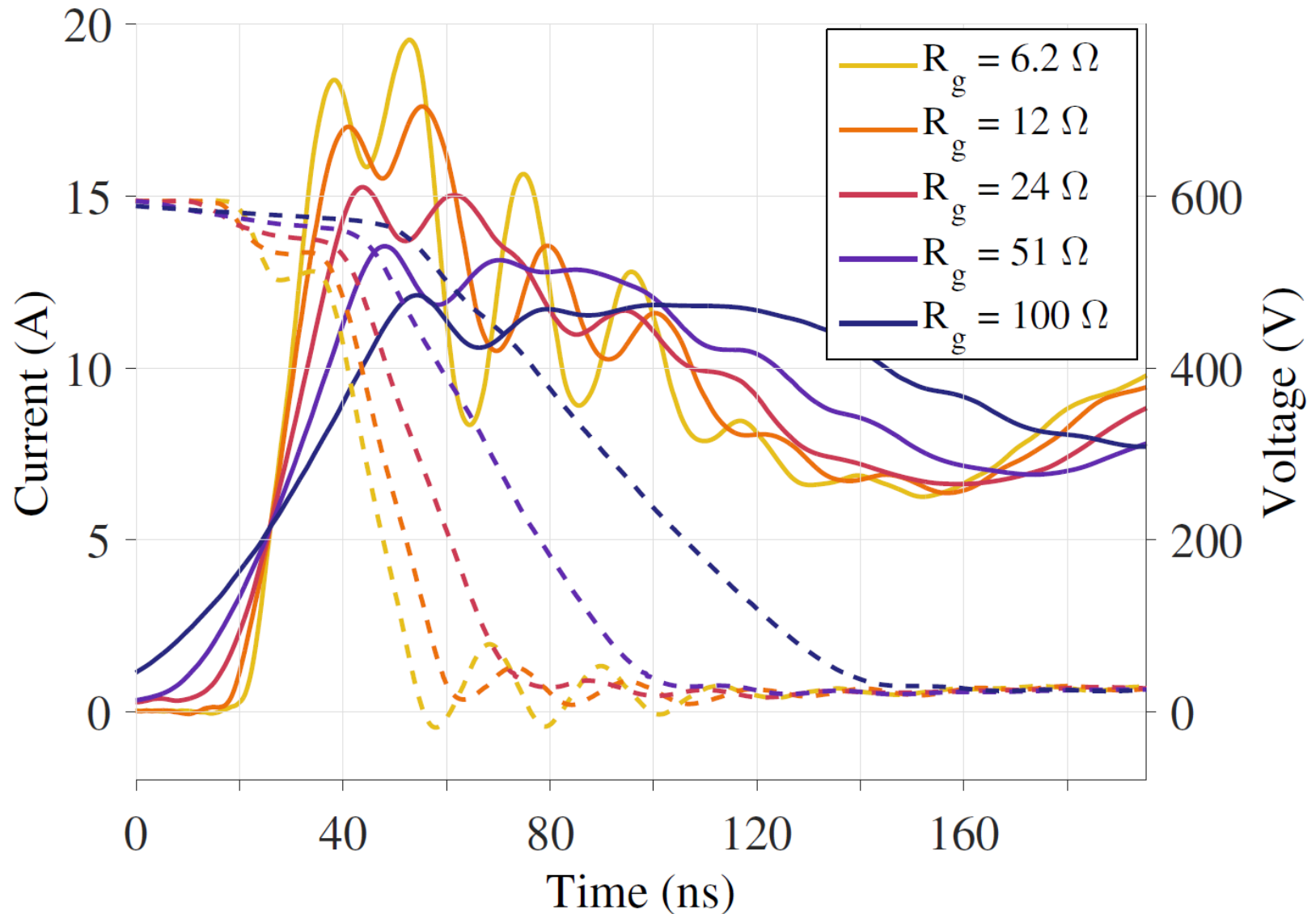
Class EF Push Pull Inverter, 13.56MHz, 500W



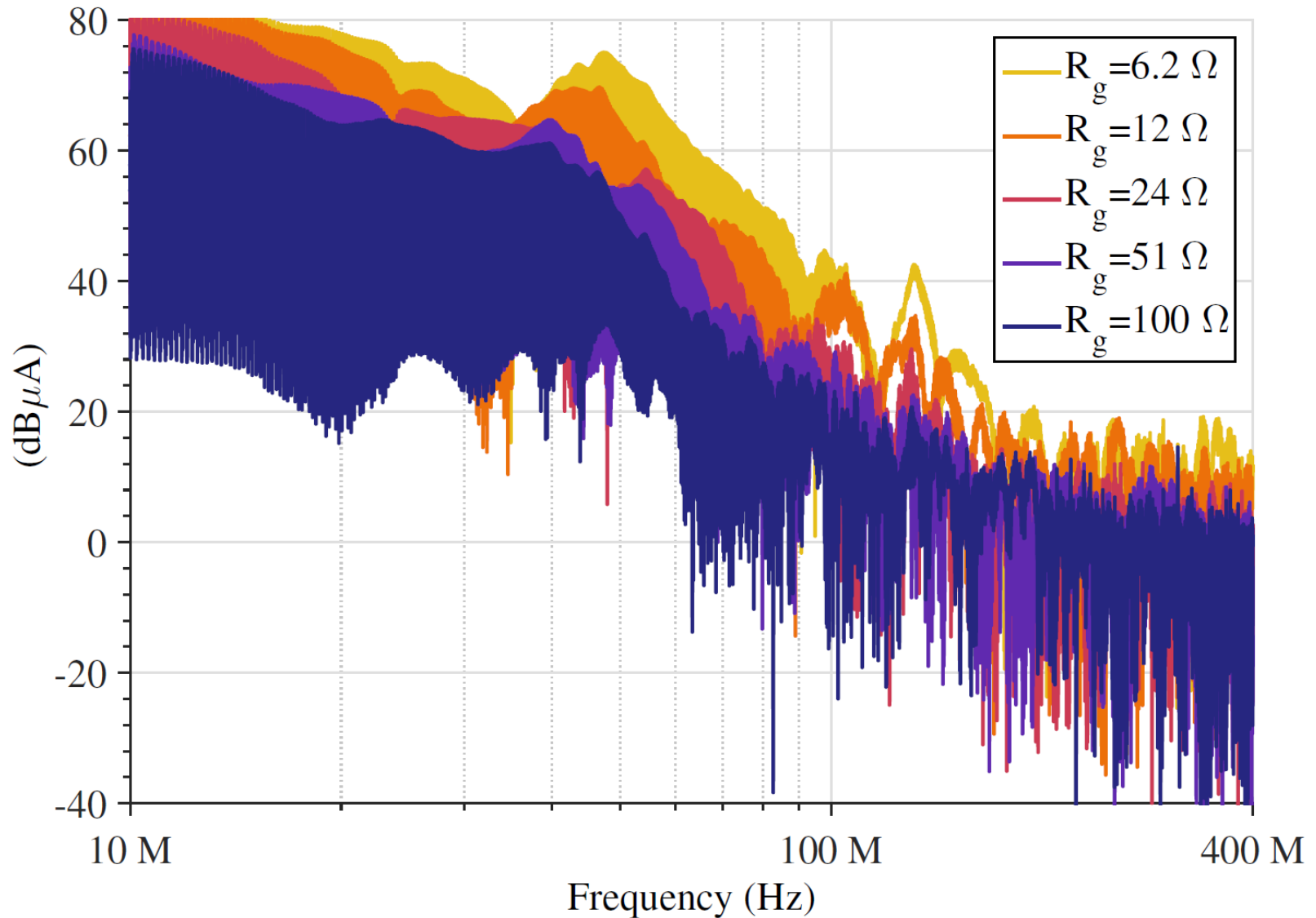
Wireless Power Transfer

Challenges with High Switching Speed (high dv/dt)

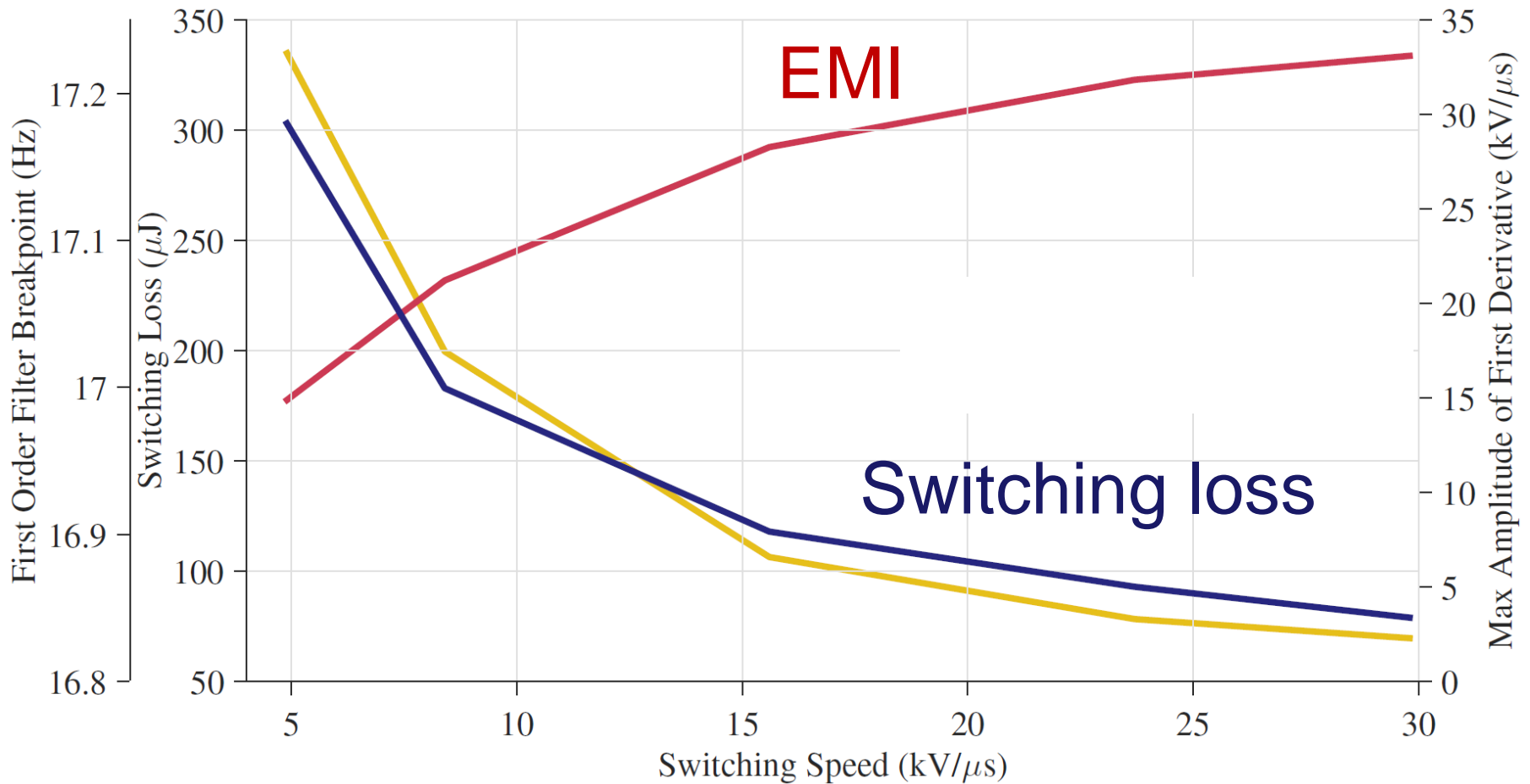
Overshoot, Oscillation, Losses, Cross-talk



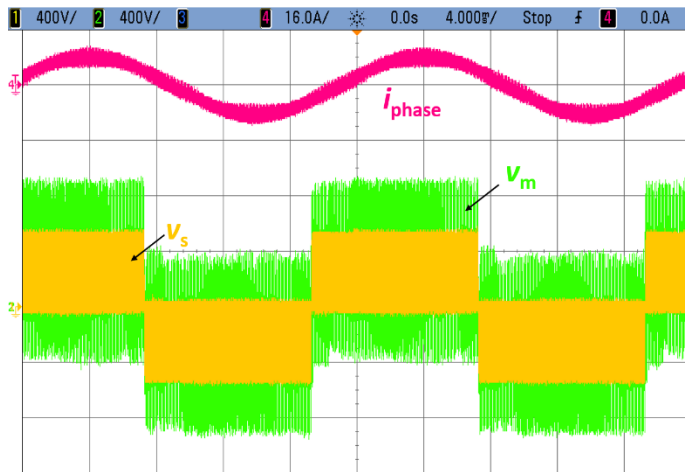
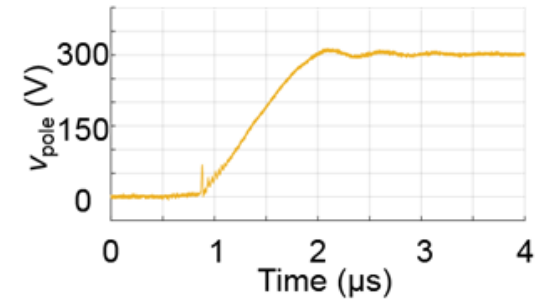
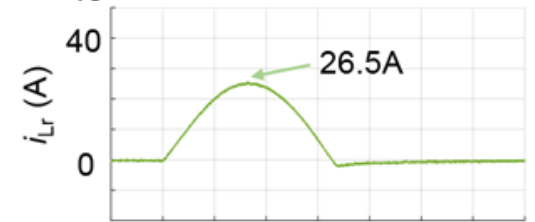
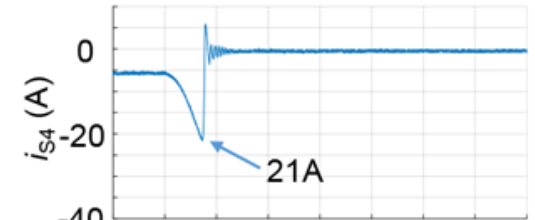
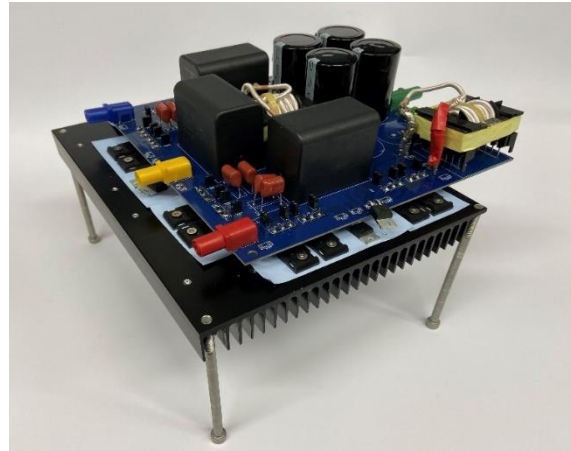
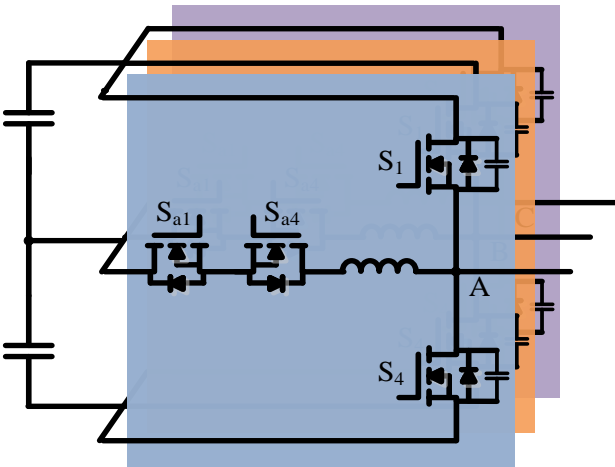
Challenges: Increased Level of EMI



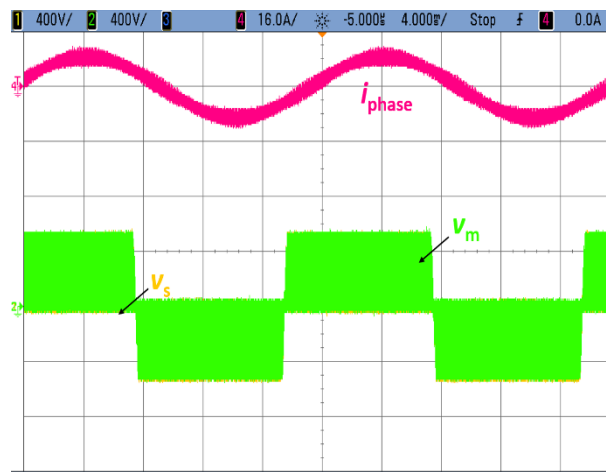
Challenges: Trade-off of EMI and Switching Loss



Potential Solutions: Soft-switching



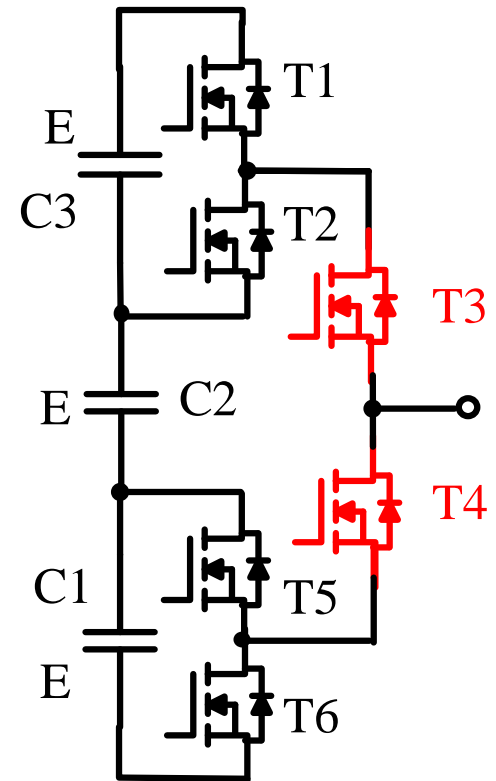
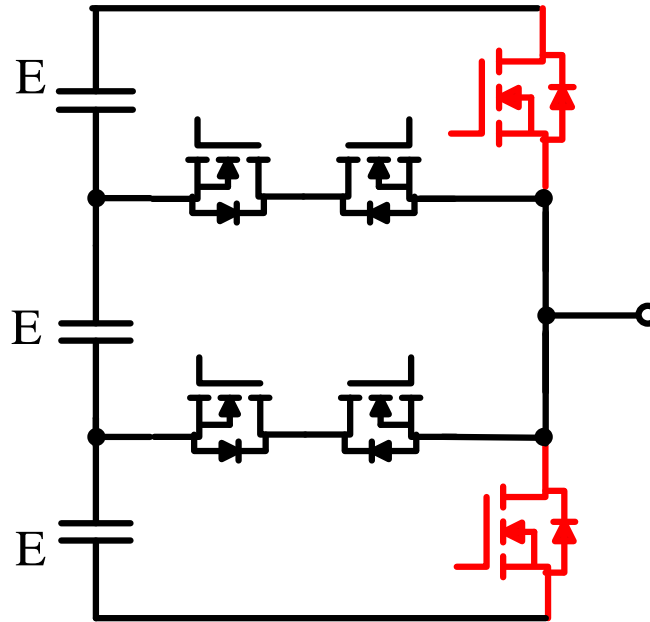
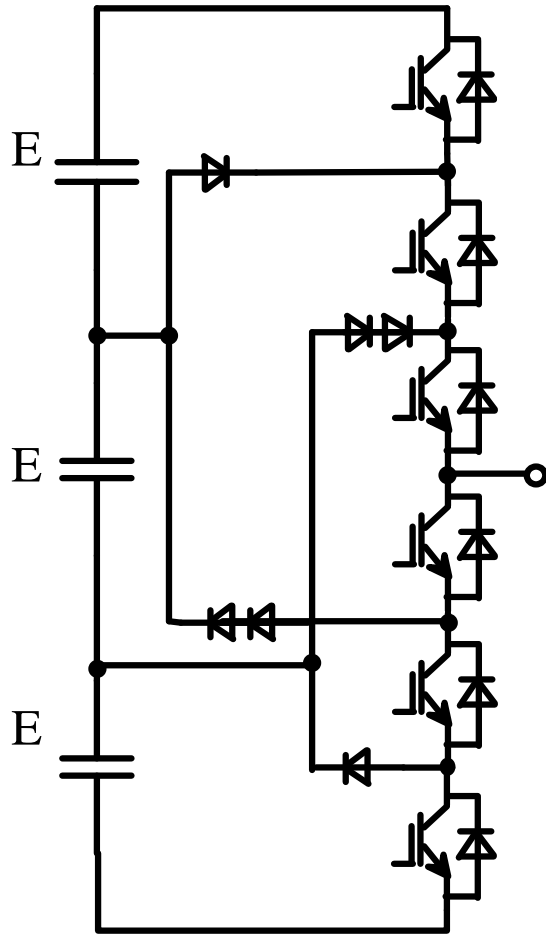
Hard switching
 $t_r = t_f \approx 50\text{ns}$



Soft switching
 $t_r = t_f \approx 200\text{ns}$

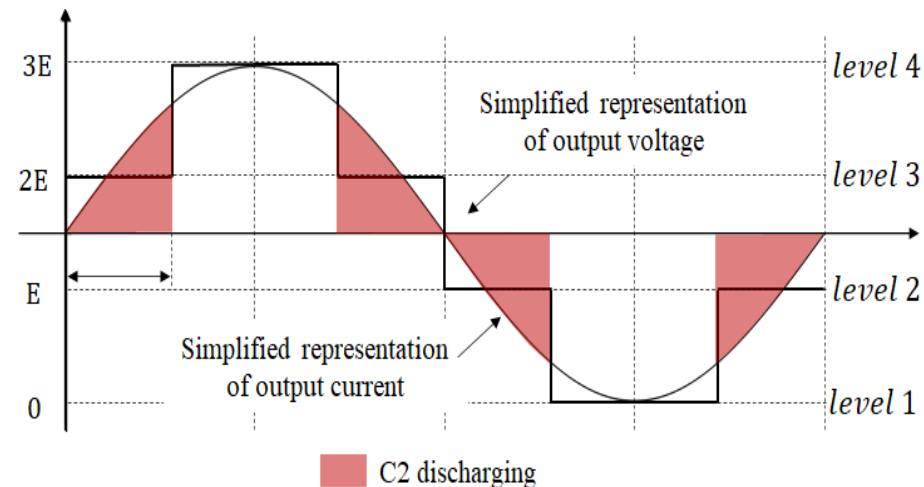
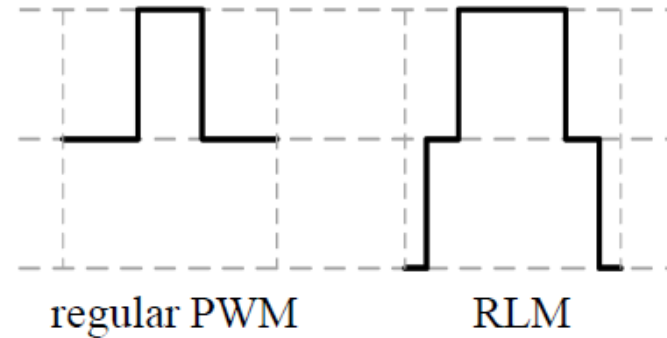
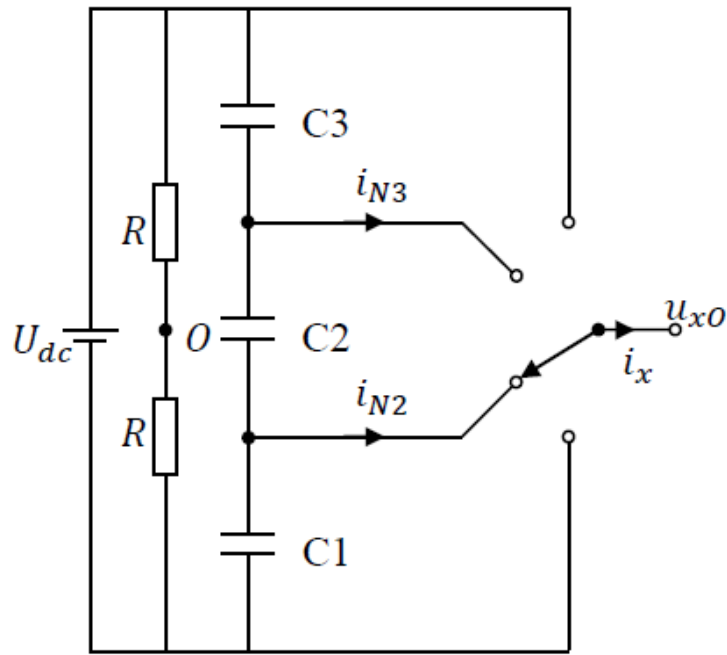
WBG devices can achieve an ideal soft-switching operation with mitigated dv/dt

Great Opportunity for WBG Device based Simplified Multilevel Converter Topologies

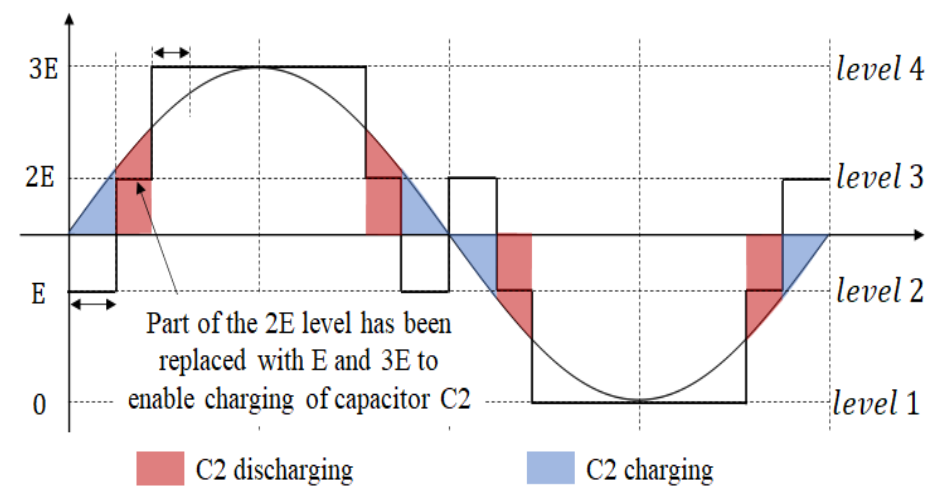


X. Yuan, J. Wang, I. Laird, W. Zhou, "Wide-bandgap Device Enabled Multilevel Converters with Simplified Structures and Capacitor Voltage Balancing Capability", *IEEE Open Journal of Power Electronics*, July 2021.

Redundant Level Modulation for Multilevel Converters

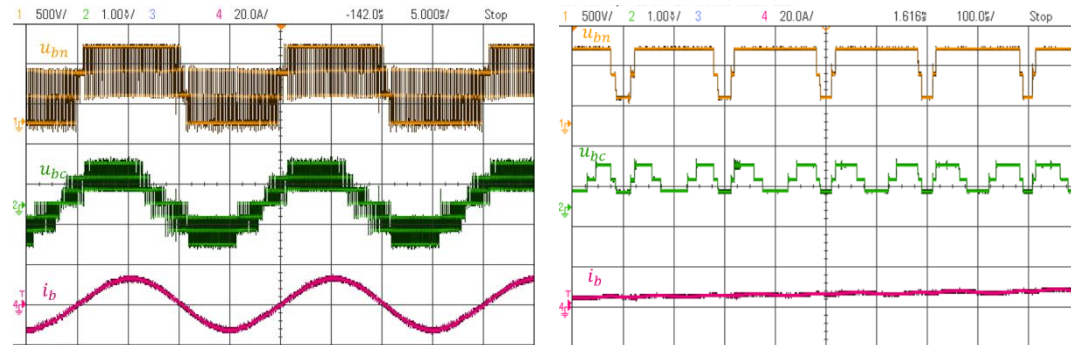
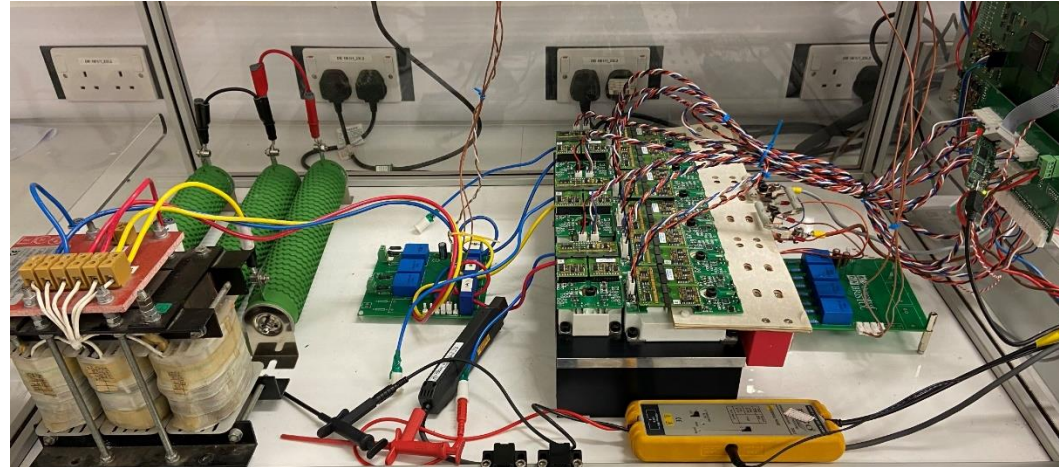
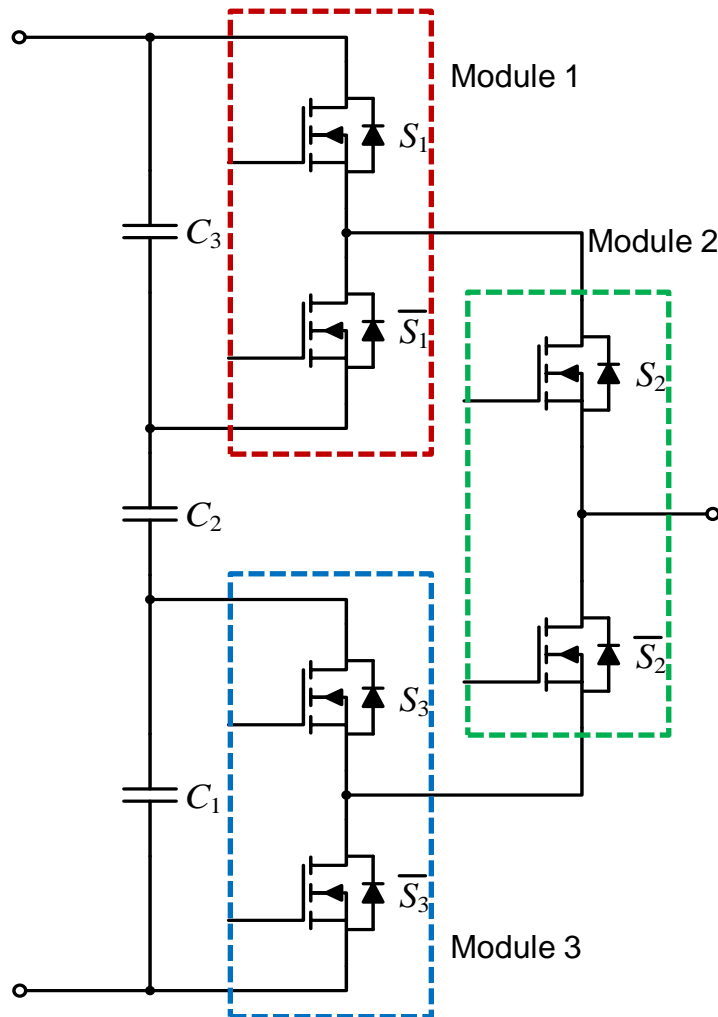


With conventional modulation



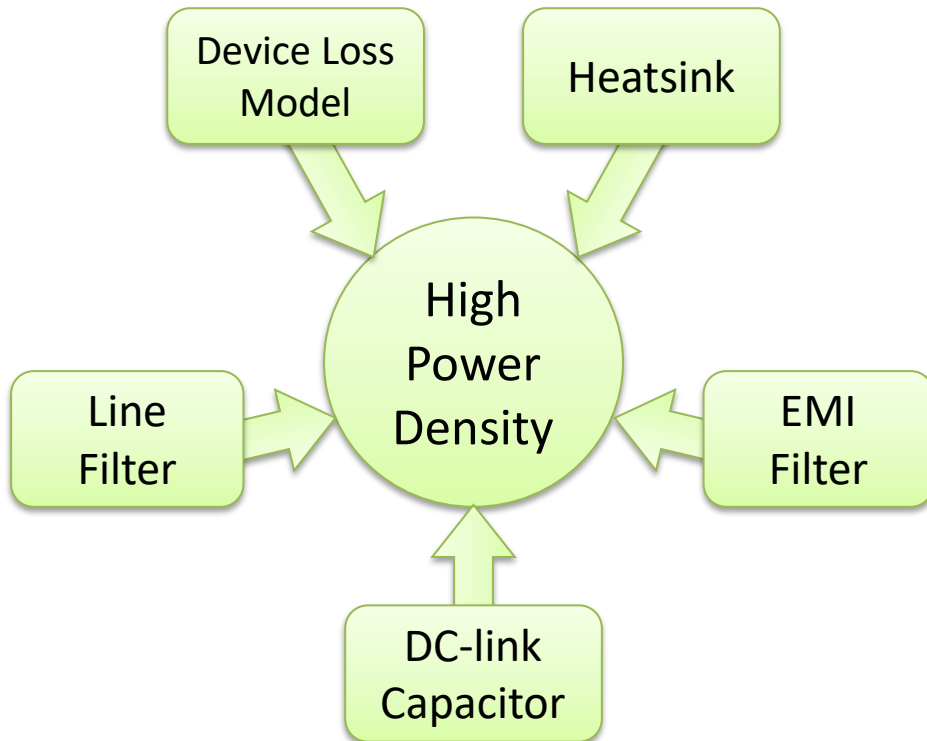
With redundant level modulation

Simplified Multilevel Topologies with SiC MOSFETs



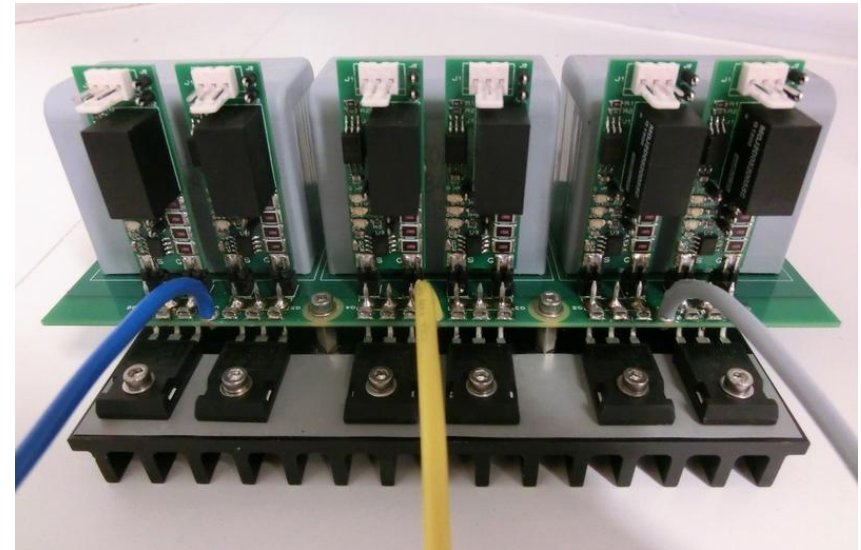
- 1kV dc voltage, 100kW
- Conduction loss = 456 W
- Switching loss = 150.6 W @ $f_{sw} = 5$ kHz; 99.4% efficiency. 98% @ $f_{sw} = 50$ kHz

Holistic Optimisation of Wide-bandgap Converters

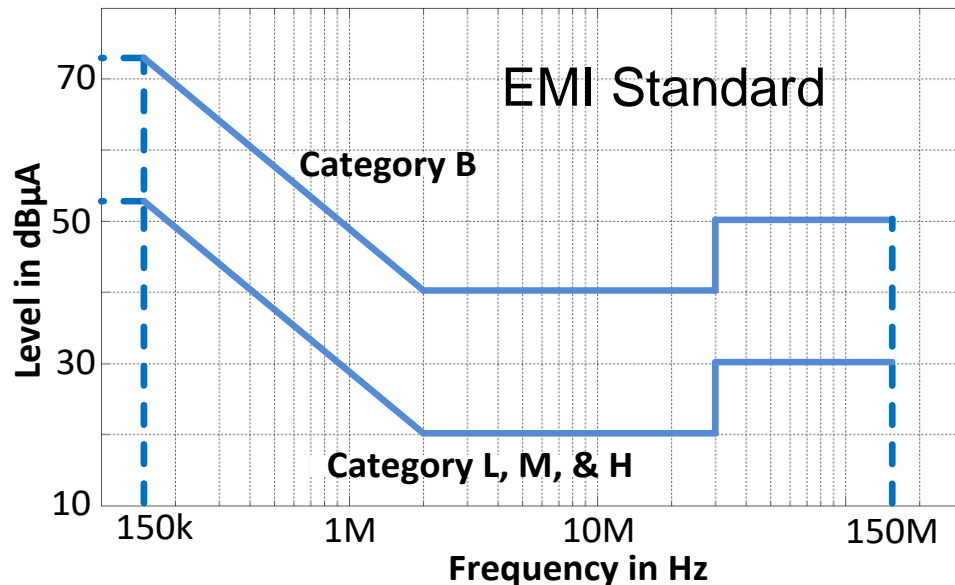


A holistic design optimisation tool has been developed.

The developed SiC converters have been used by several companies and universities.

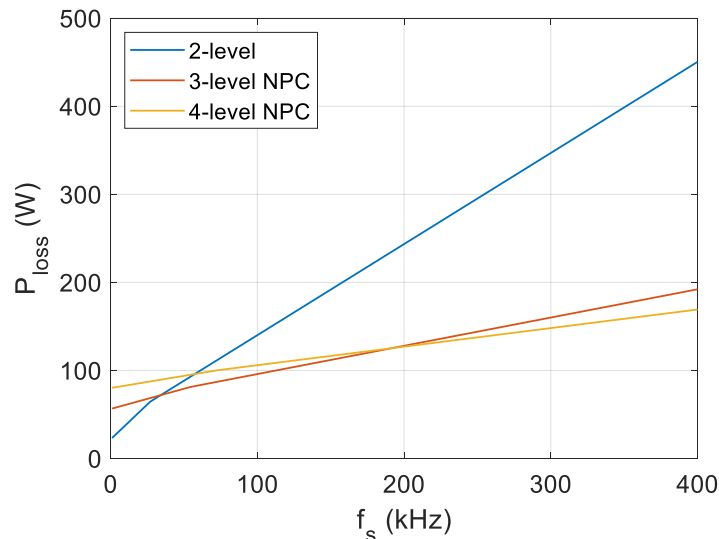


5kW, three-phase SiC DC/AC converter

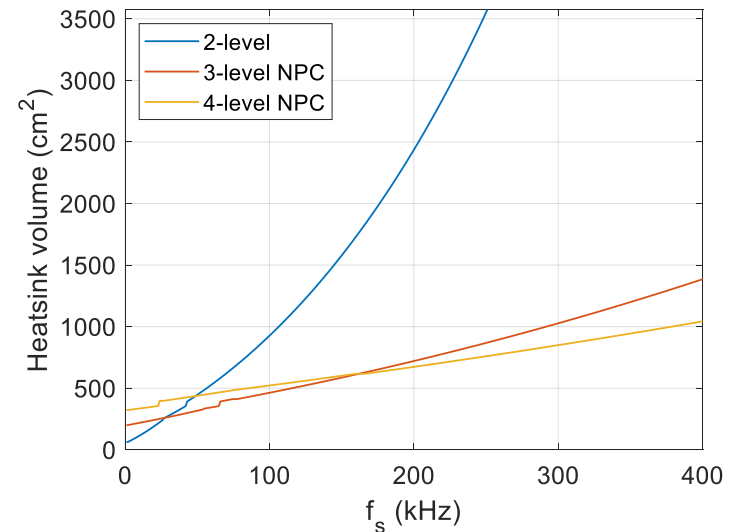


Multi-Level Design Tool

- Tool simulates a range of switching frequencies, calculating power losses and its impact on component volumes (switching devices, cooling system, filters etc.)
- Facilitates side-by-side comparison of converters with differing
 - topologies
 - number of levels
 - device technology

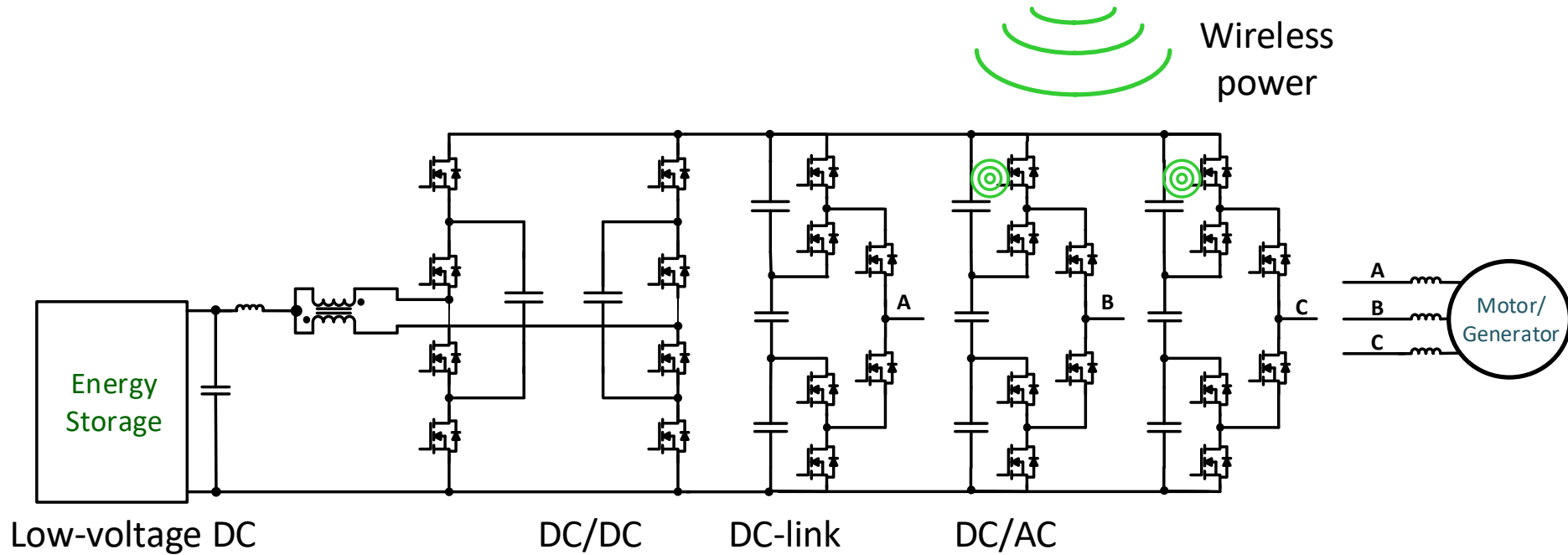


Switching device P_{loss} vs Switching frequency

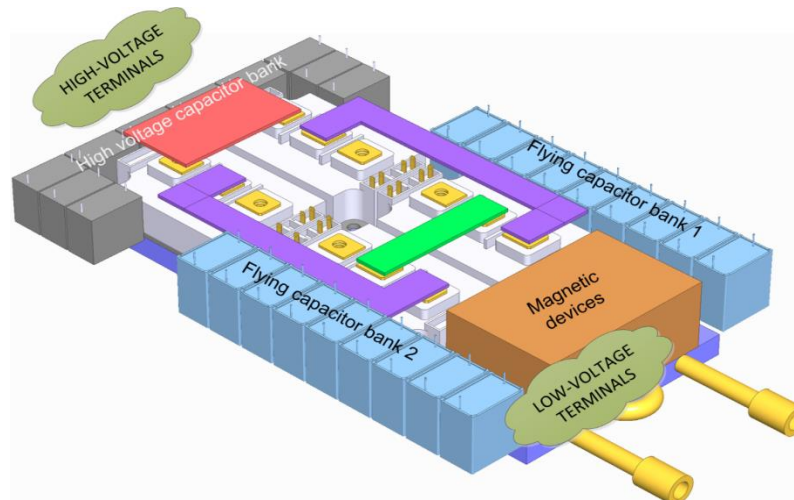


Heatsink volume vs Switching frequency

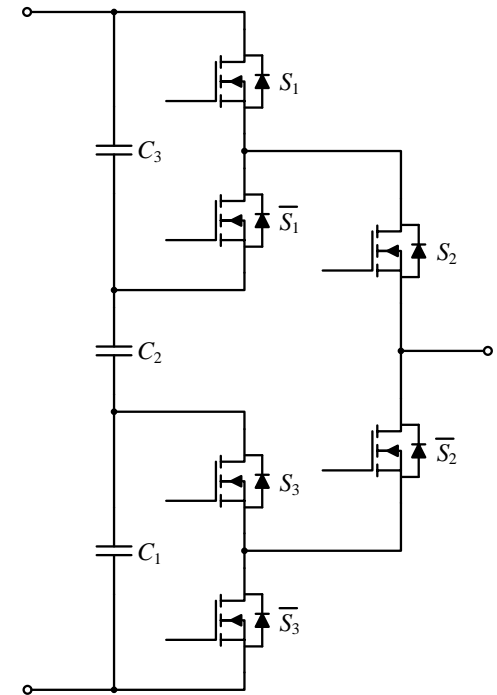
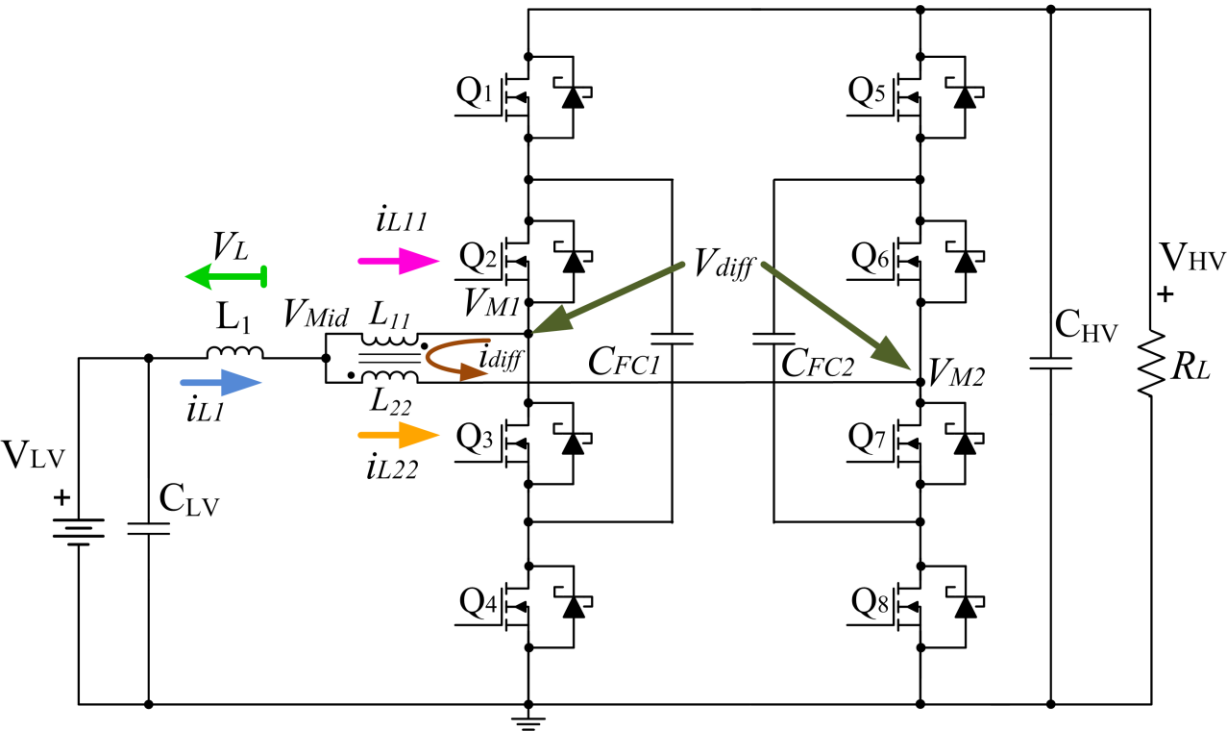
Project Demonstrator



Rated at 1200V, 100kW



High Power DC/DC and DC/AC Converters

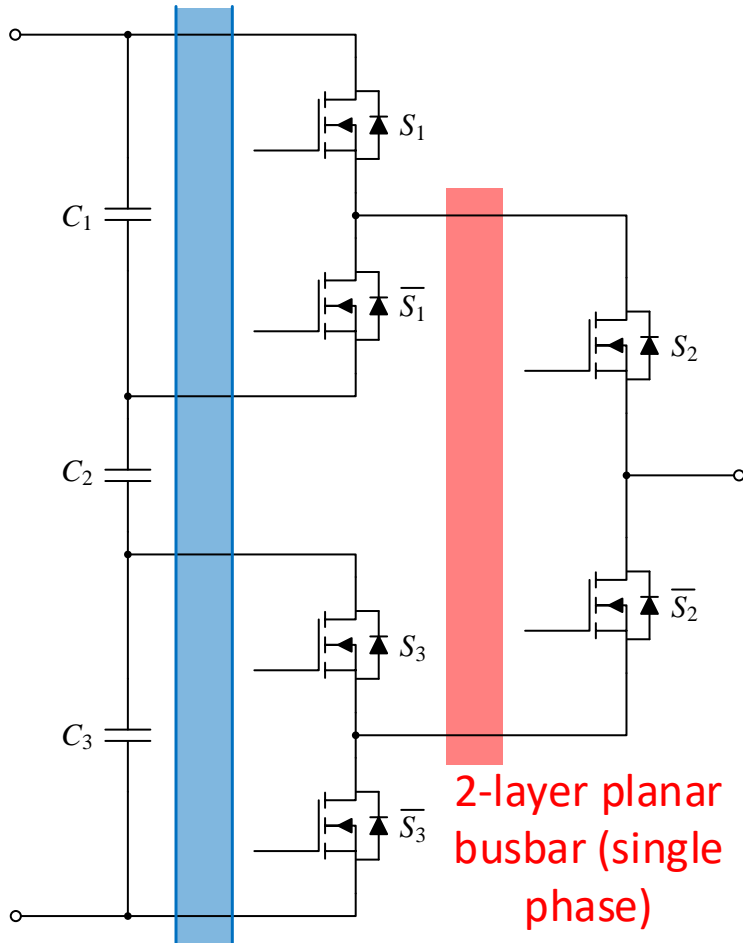


Three-level flying capacitor based dc/dc converter

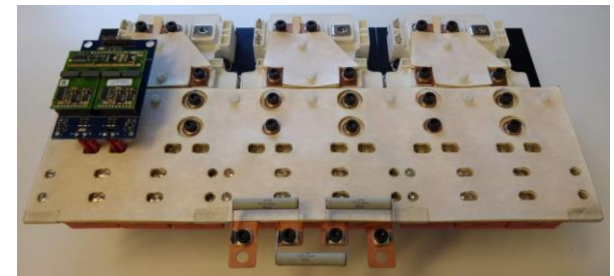
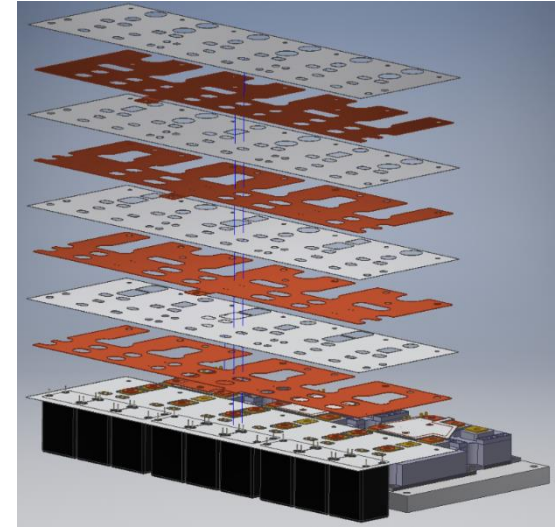
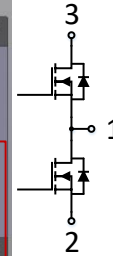
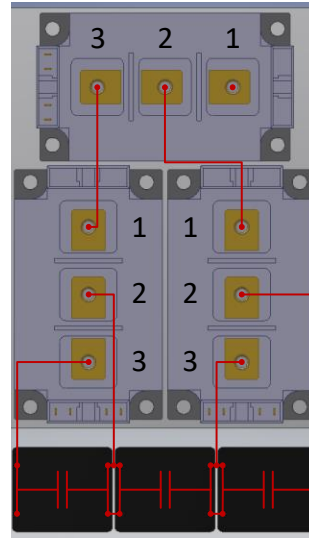
Four-level dc/ac converter

Four-level DC/AC Converter

4-layer planar busbar (3-ph)

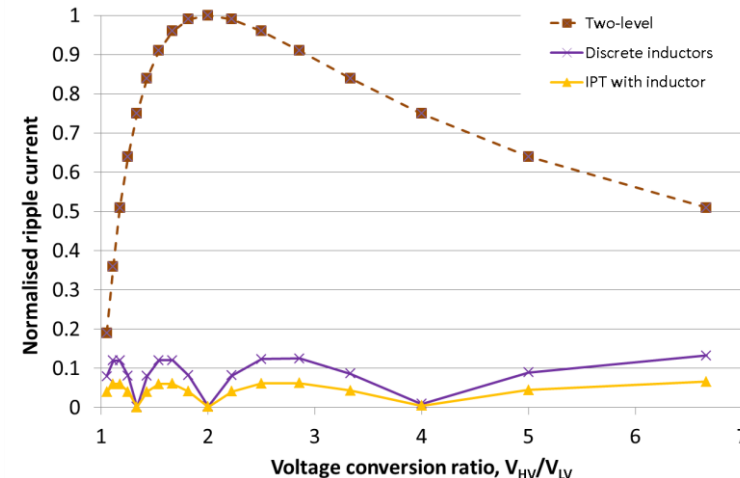
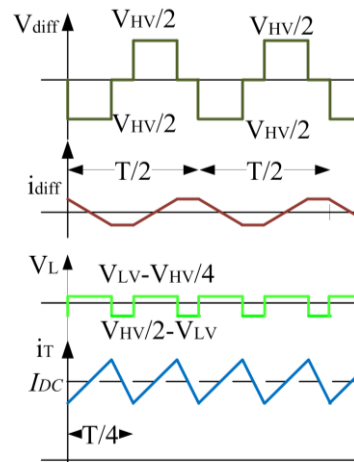
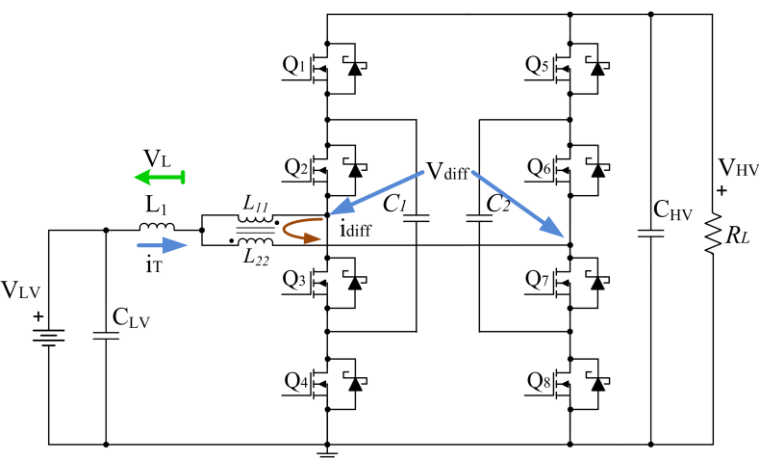


2-layer planar
busbar (single
phase)



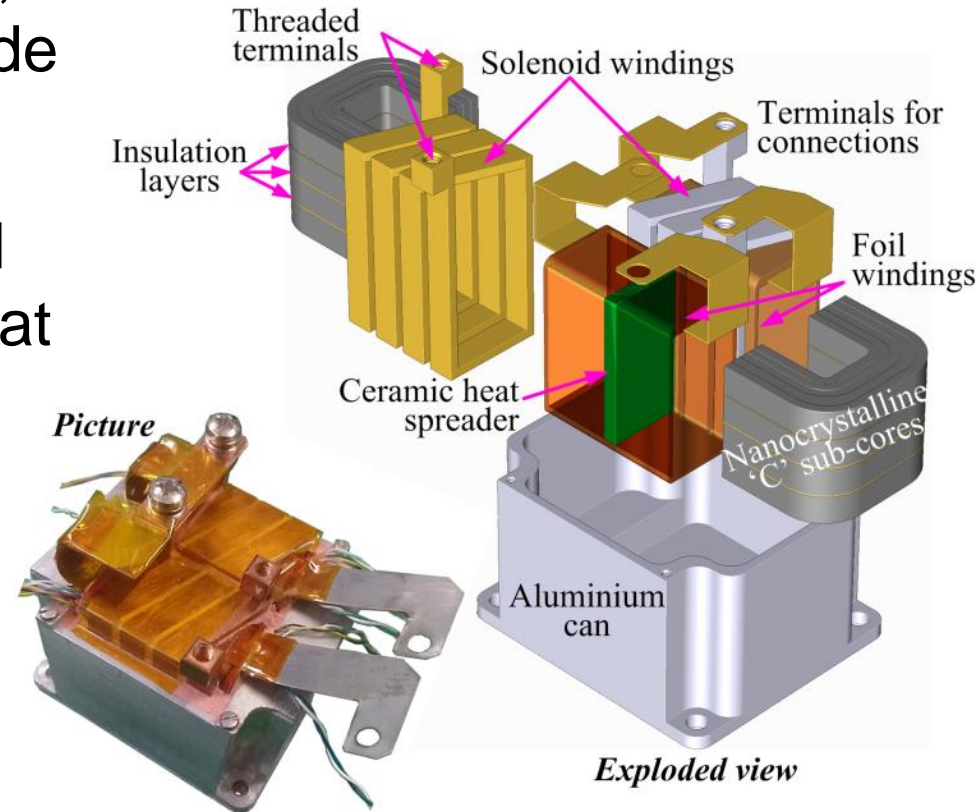
High Performance DC-DC Conversion

- Aiming to increase voltage and power and reduce overall size
 - Interleaved (90°) flying capacitor legs
 - Device voltages $V_{HV}/2$
 - Leg output voltages at $2f_{\text{switching}}$ with reduced voltage steps
 - With two separate inductors the overall input ripple is almost 10x smaller compared with a single two level converter
 - Interphase transformer and one inductor reduces ripple by almost 20x and inductor operates at $4f_{\text{switching}}$ → small size
 - Active balancing of phases and capacitor voltages needed



Reducing the size of DC inductors

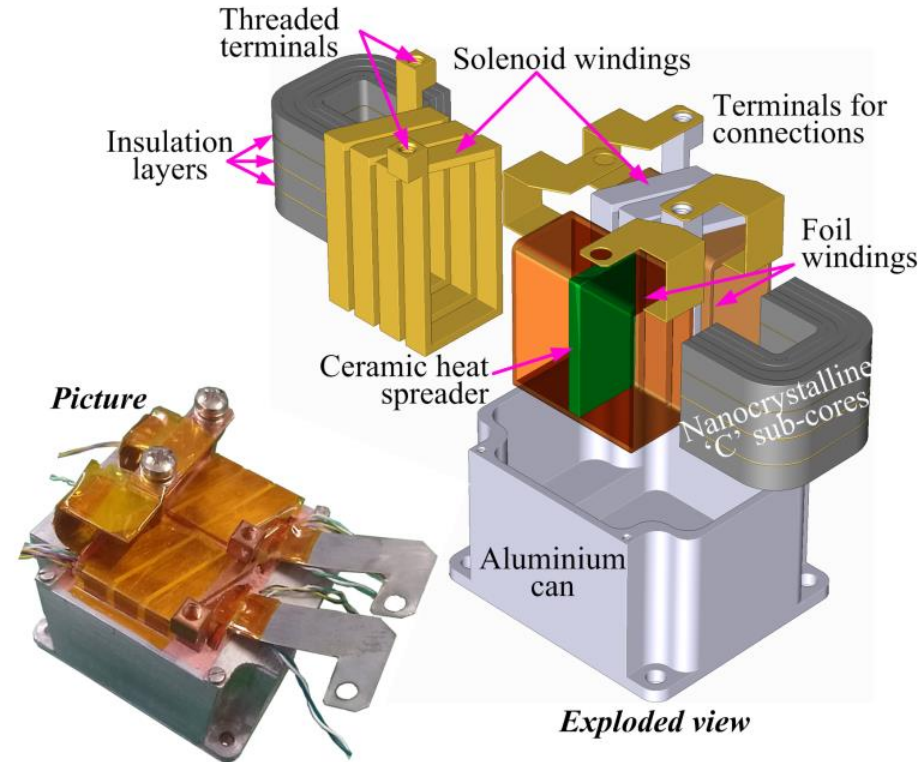
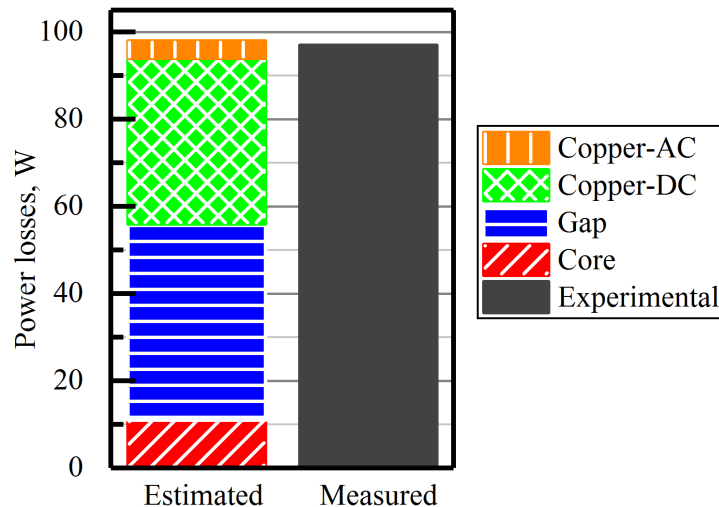
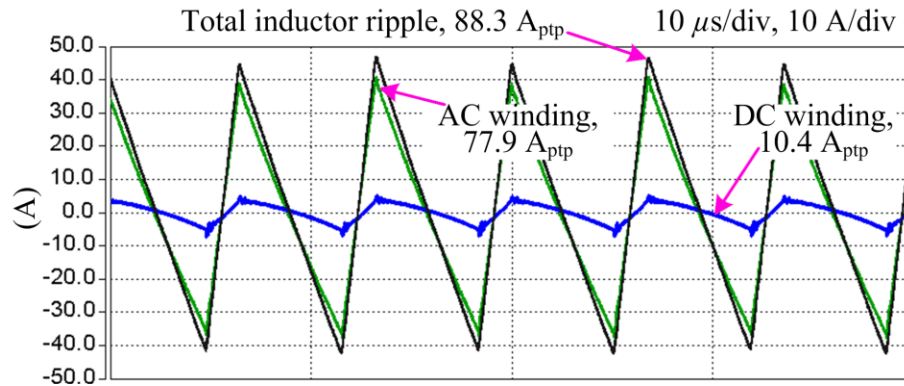
- To reduce gap losses in tape-wound, nano-crystalline cores, stack smaller cores side-by-side
 - 50% reduction with three cores
- To improve heat flow in potted components place ceramic heat spreaders in the airgaps
- To reduce copper losses combine solenoidal winding (low DC resistance) with foil winding (low AC resistance)



G. Calderon-Lopez, R. Todd, A. Forsyth, J. Wang, X. Yuan, S. Aldhaher, C. H. Kwan, D. Yates, P. Mitcheson, “**Towards Lightweight Magnetic Components for Converters with Wide-bandgap Devices**”, in *Proc. IEEE ECCE-Asia (IPEMC) '20 Conf.*, pp. 1-6, November, 2020.

Reducing the size of DC inductors

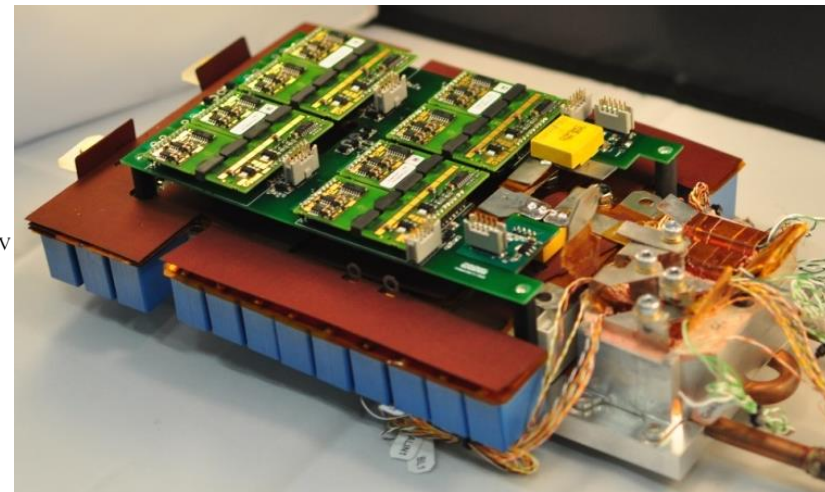
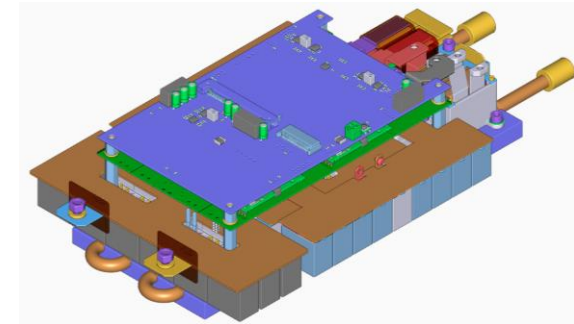
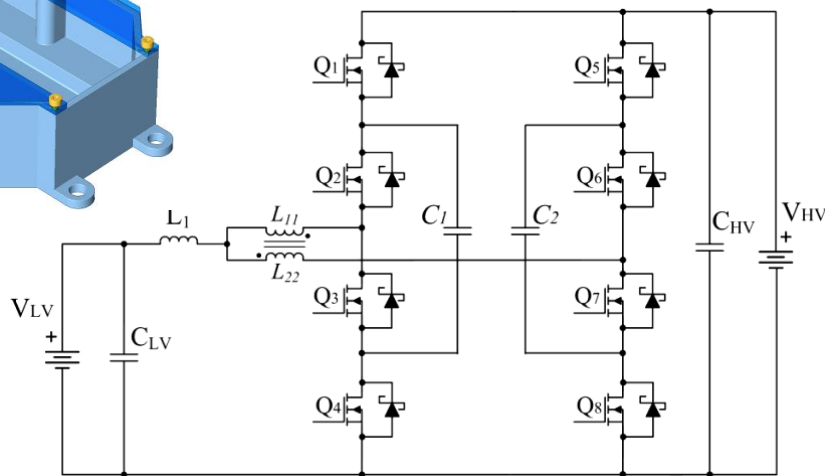
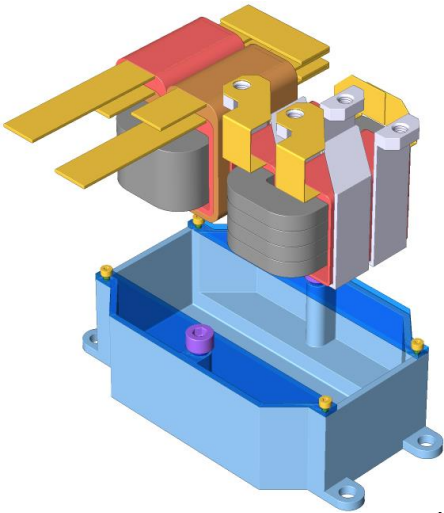
- 50% weight and volume reduction in a 5 μ H, 200 A, 150 kHz inductor



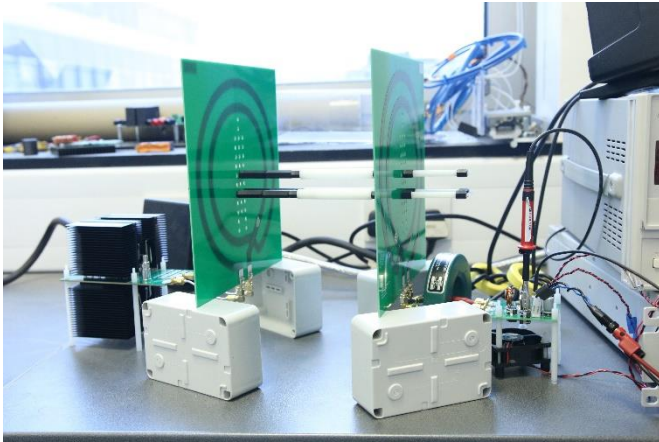
Measured AC current sharing, and estimated and measured losses:
 $I_{DC} = 160$ A, $\Delta I_L = 88.3$ A, ~ 148 kHz.

Demonstrator

- 100 kW, 1200 V DC-DC converter demonstrator
 - SiC MOSFETs, 80 kHz switching, 320 kHz inductor ripple
 - Overall weight 4.2 kg, (potted magnetics 0.7 kg)
 - 23.8 kW/kg and 31.8 kW/litre
 - Efficiency 96.8%



HF-IPT to power gate drives

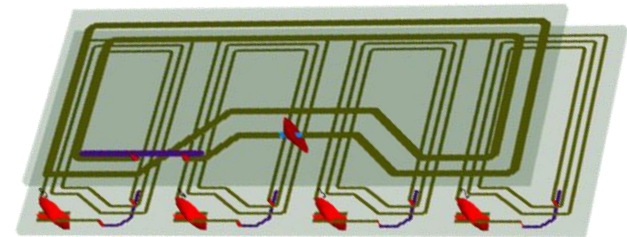
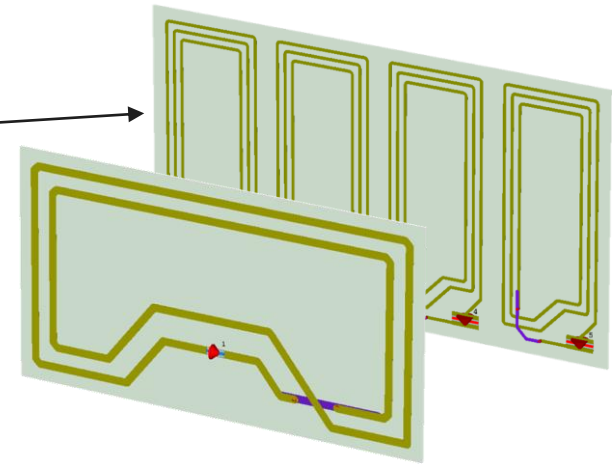


- Wireless power is extended from work in Tranche 1
 - We demonstrated a one-to-one system with 80%+ efficiency
 - Constant current transmitter gives a starting point for multiple receivers
- Advantages of using high-frequency inductive power transfer systems to power floating gate drives:
 - Provides very large isolation for applications such as HVDC
 - Minimises the mass of the magnetic components
 - Multiple receivers at very different voltage levels can be powered from a single power source
 - Common-mode transient immunity

HF-IPT to power gate drives

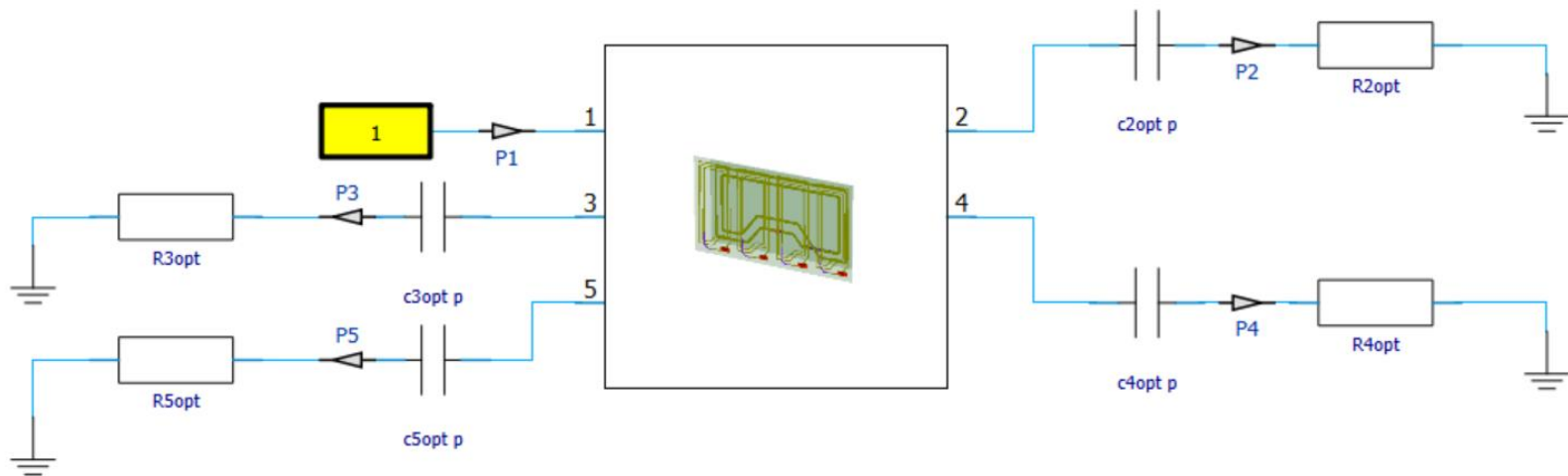
- Design 1

- 4 identical receiver coils
- 1 transmitter coil
- Metal shield around system
- Distance between TX and RX PCBs is varied from 5mm to 50mm in steps of 5mm
- FR4: Thickness of 1.6mm
- Copper: 35 μm (1oz)
- CST simulations of the link one to four link



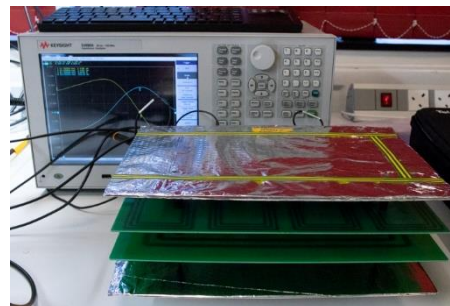
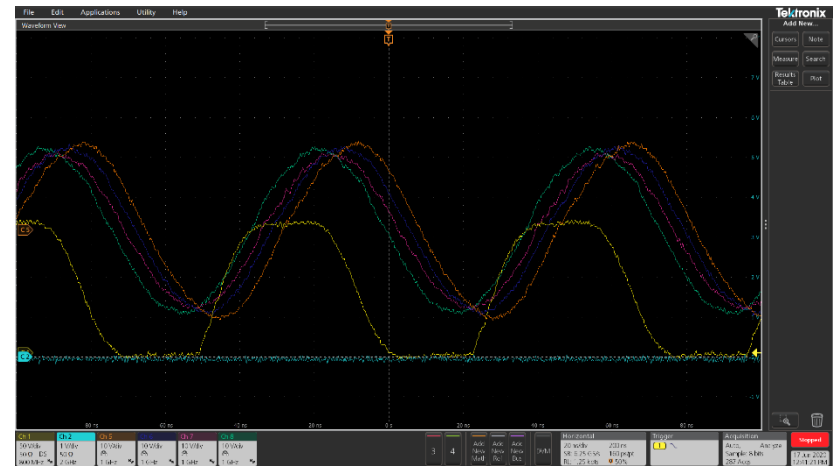
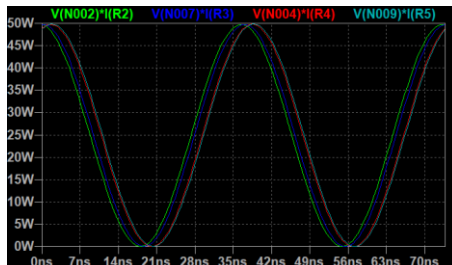
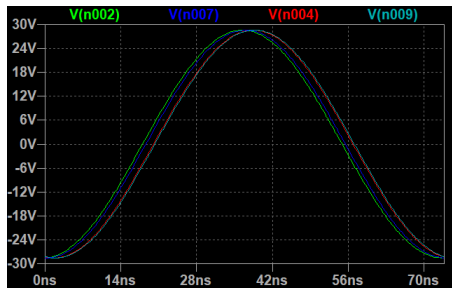
System optimisation

- Tuning the link with series capacitances
 - Using CST Studio Suite's Circuit Optimiser
 - Algorithms: Trust Region Framework, Nelder Mead Simplex Algorithm, Interpolated Quasi Newton
 - Design parameters: Receiver loads, receiver tuning capacitances, transmitter (P1) current



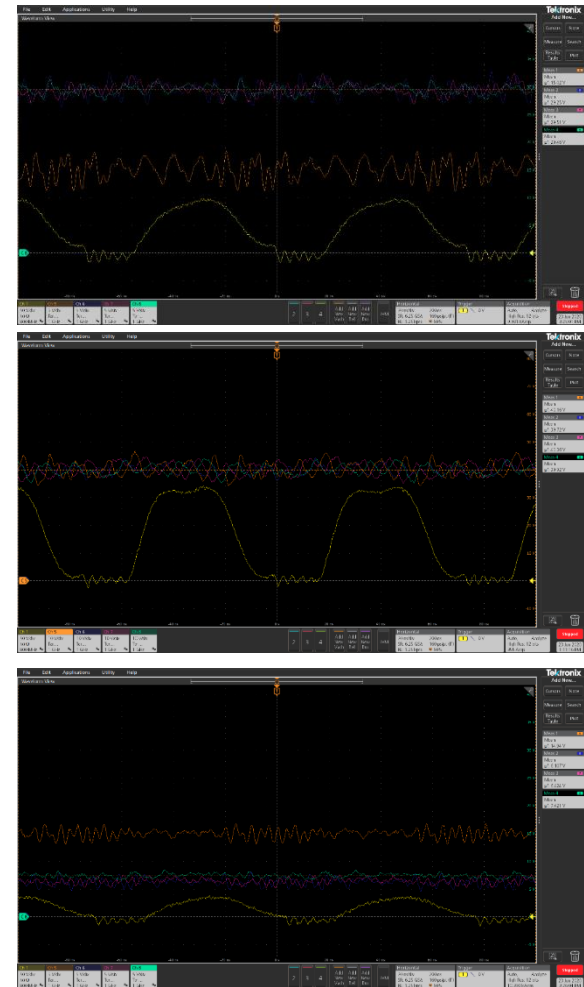
LTSpice vs experiments

- Spice simulations from the design obtained from CST
 - The loads are evenly distributed
- Tuning the receivers with the design 1
- Waveforms are similar yet there is a slight unbalance



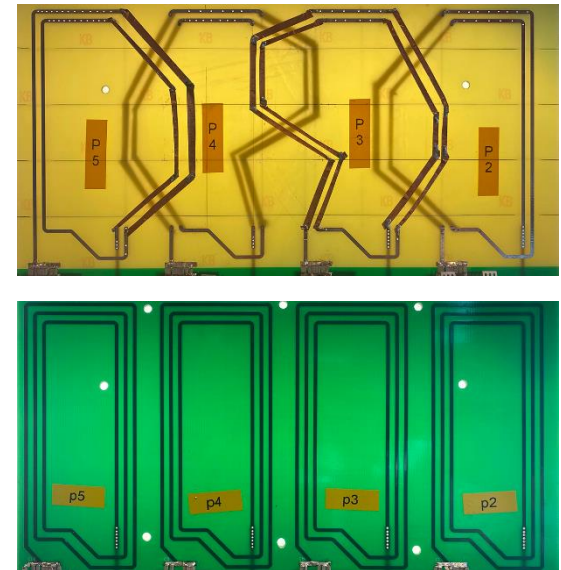
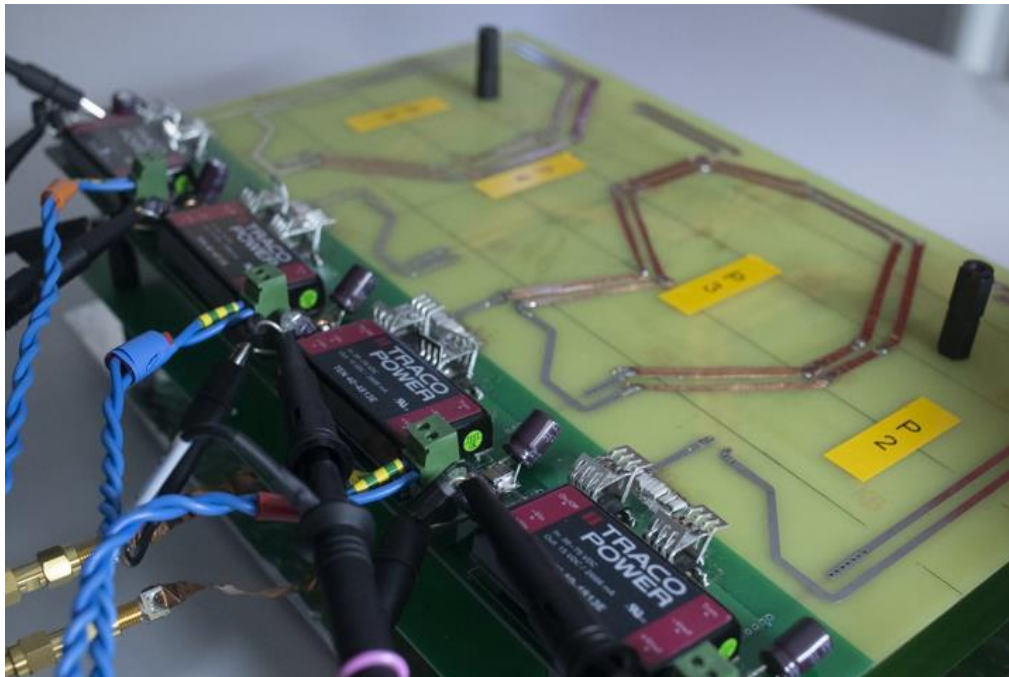
Design 1 in operation

- Powering independent regulated loads using design 1
 - When the dc loads are the same, they are balanced
 - When the primary current is regulated to keep one voltage at 15V and the loads differ, there is a large difference between the receive voltages making the system unpractical



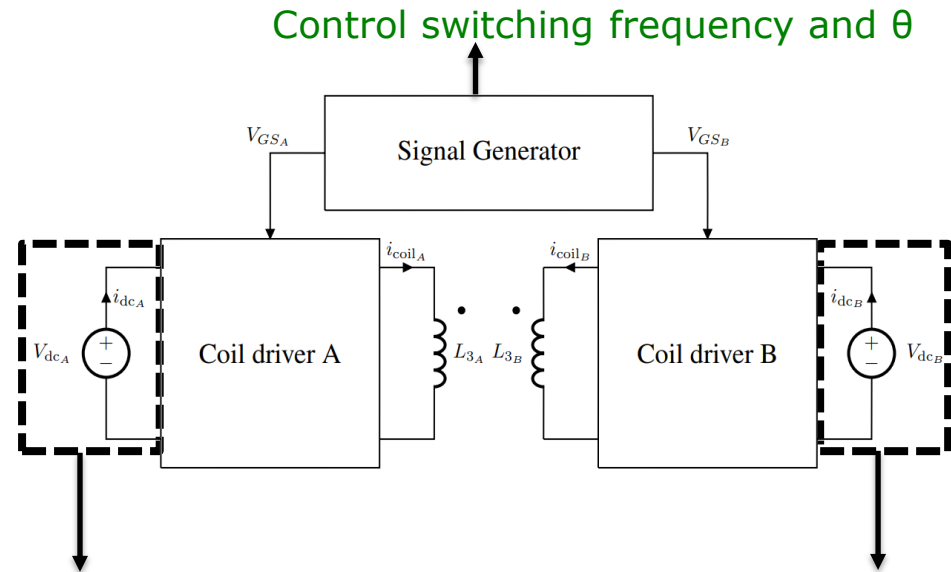
Re-spin of the receiver coils

- Design 2
 - Minimises the coupling factor between the receivers
 - Avoids the loading effects from secondary to secondary
 - We manage to get 12.5W at each output, load independent

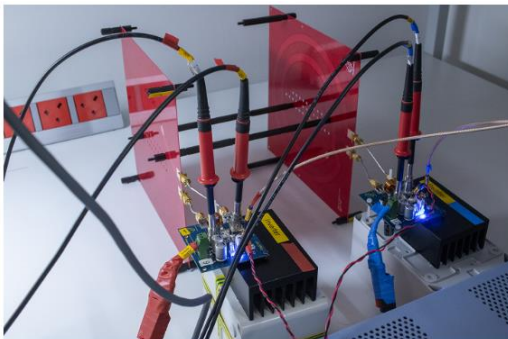


Synchronous rect./ Bidirectionality

- For the first time we showed a load independent Class EF transceiver as bidirectional coil driver!
- Active control of power flow
- Correction of tuning mismatches
- Low coupling operation
- Fully autonomous environments operation
- Powering systems in low accessibility areas

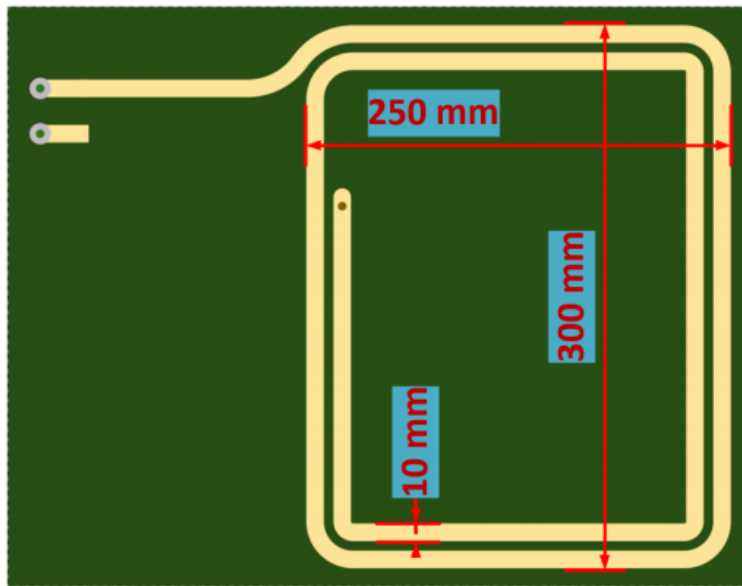


Source-sink configuration of CV electronic load to keep a fixed dc voltage

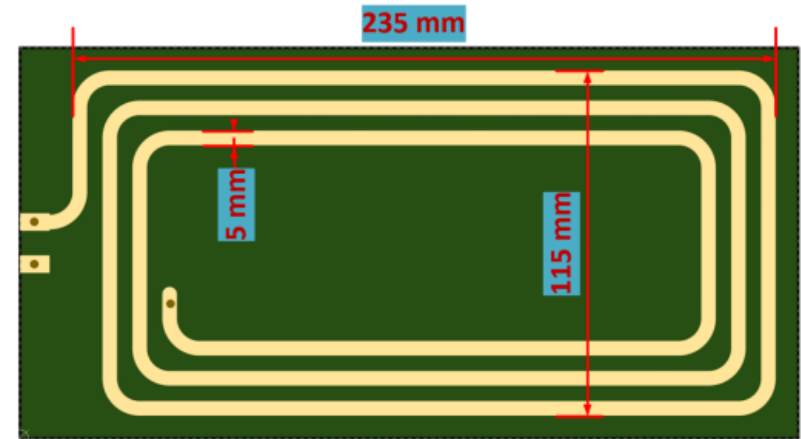


E-Scooter Wireless Charger

- Transmit pad



- Receive unit



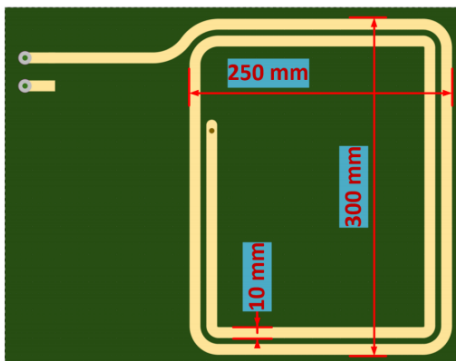
Wurth Elektronik
364003 flexible ferrite
sheets

E-Scooter Wireless Charger

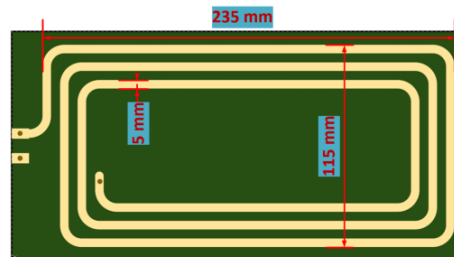


- Integration of receive unit in bottom of e-scooter
- Distance 65 mm to 80 mm from transmit pad

- Transmit pad



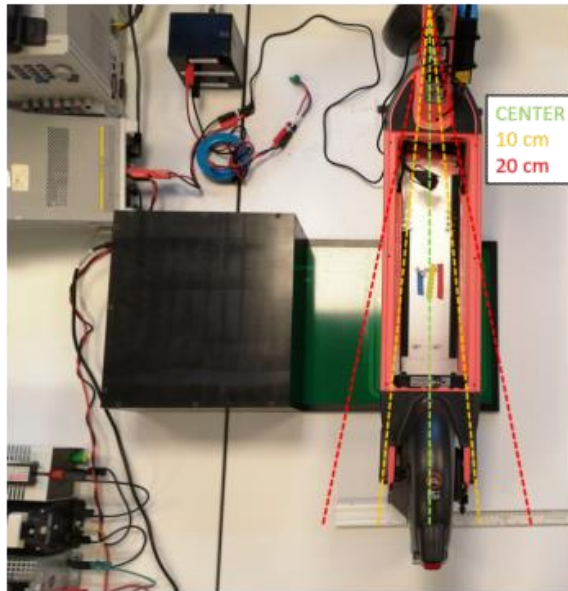
- Receive unit



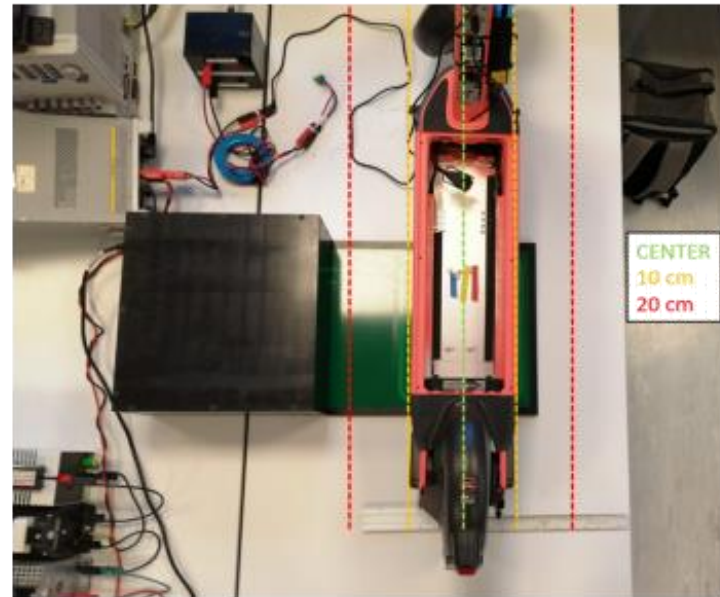
Würth Elektronik
364003 flexible ferrite
sheets

E-Scooter Wireless Charger

- Back-wheel



Lateral



- A 6.78 MHz, 110 W wireless charging system with DC-DC IPT efficiency of 69%-75% was successfully integrated into an E-scooter.
- Ferrite shielding, PCB coils, and high frequency resonant power converters were used.

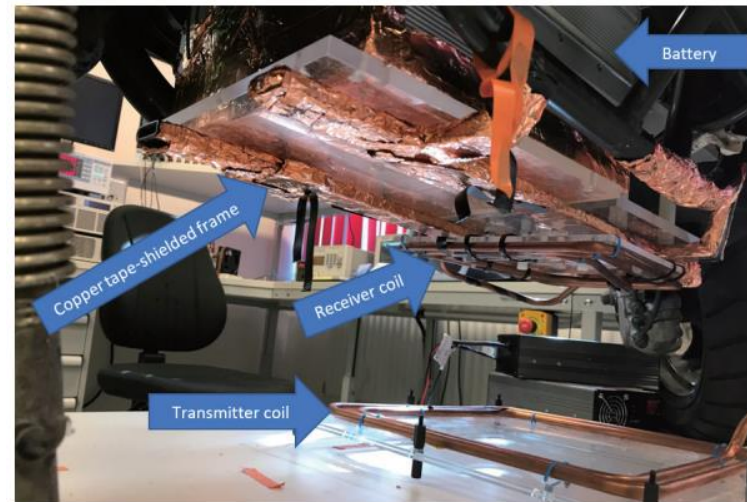
Integration into applications

- A 6.78 MHz, 100 W wireless charging system with DC-DC IPT efficiency of 70% was successfully integrated into an M100 DJI drone



Wireless Power Lab drone landing

- A 6.78 MHz, 600 W wireless charging system with DC-DC IPT efficiency of 85% was successfully integrated into Govecs E scooter



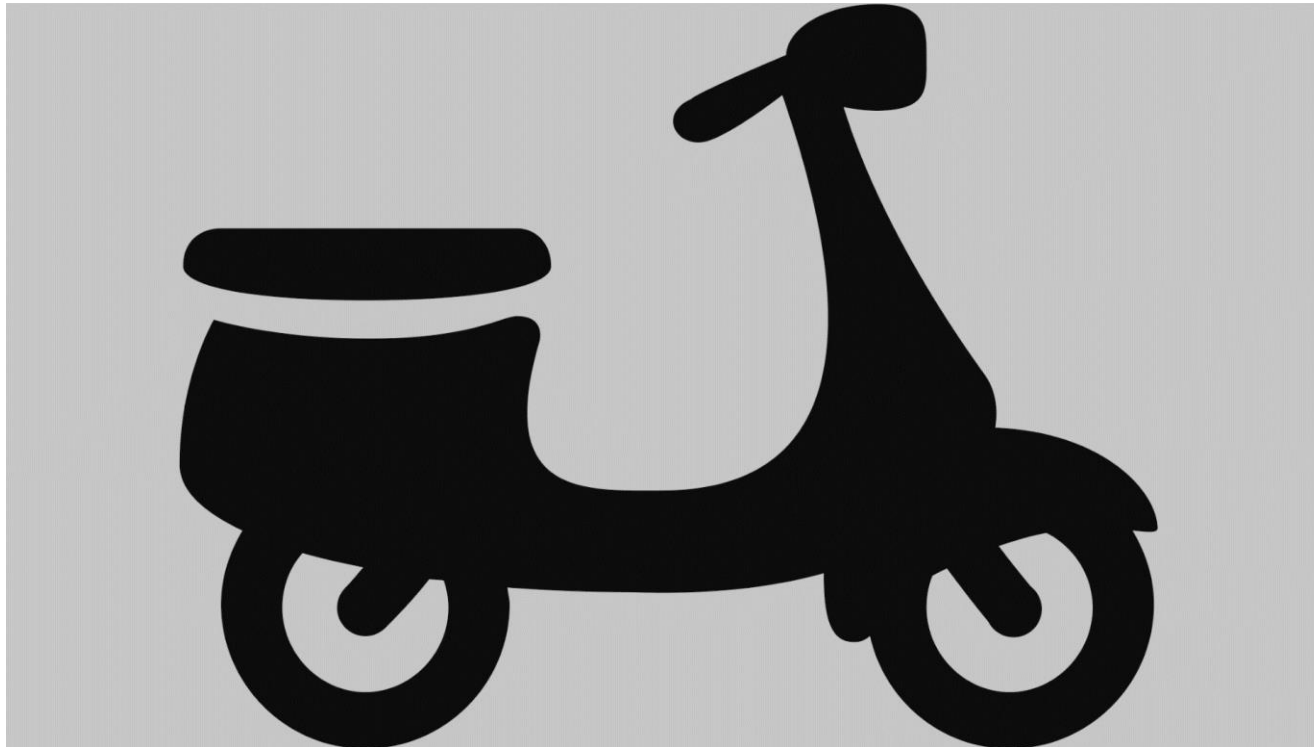
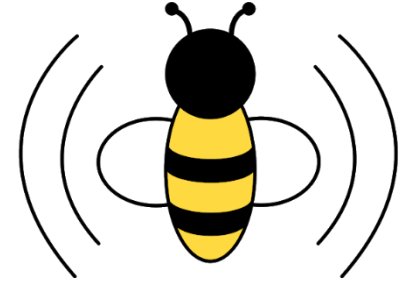
Outreach

- We hosted IEEE Wireless Power Week
 - We held a session on the future of WBG devices with participation of the Converter Architectures Theme



Bumblebee Power

- We spun out a company called Bumblebee Power to commercialise the HF-IPT technology developed during the period of the Centre for Power Electronics



Thank you!

